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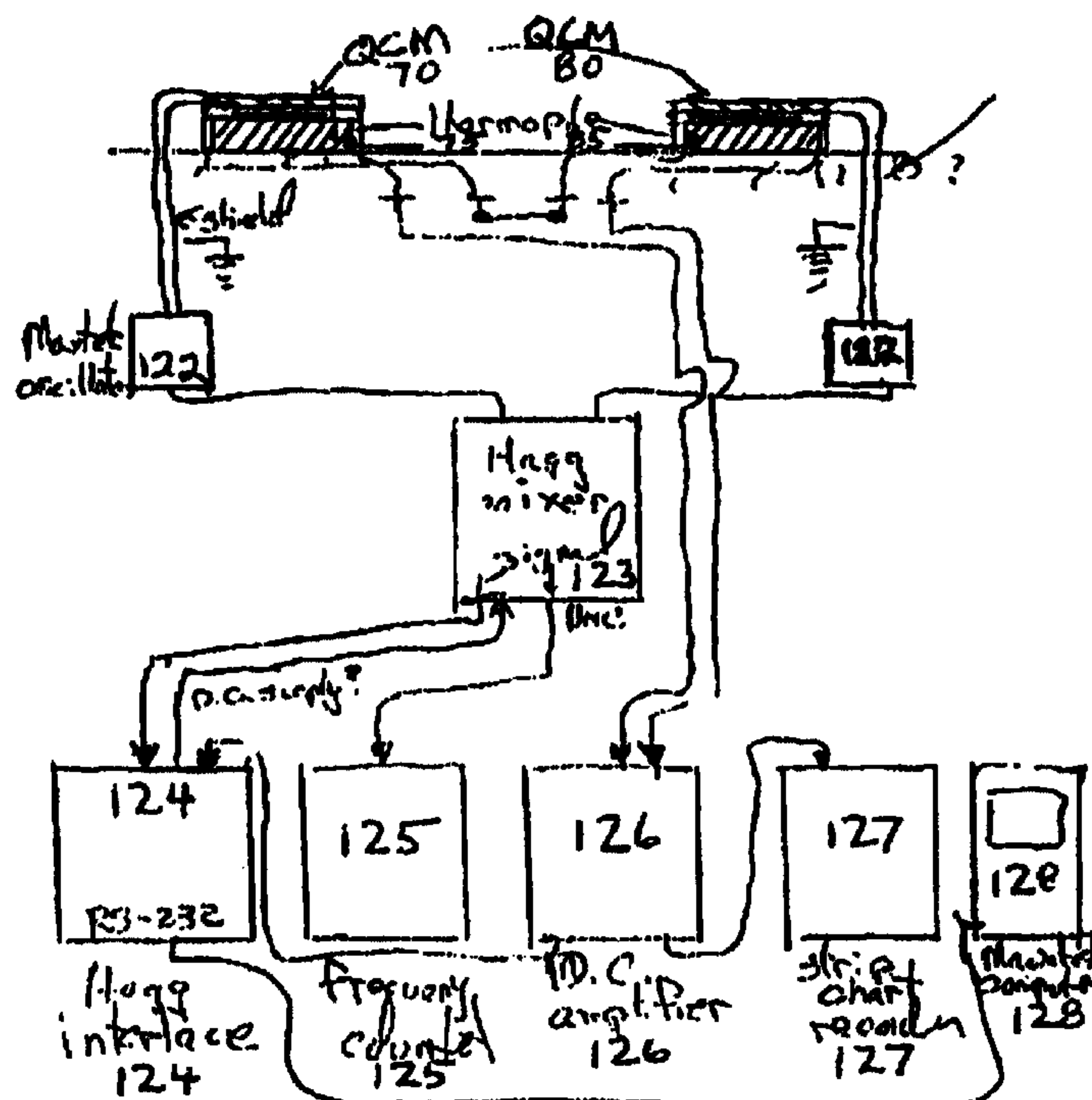
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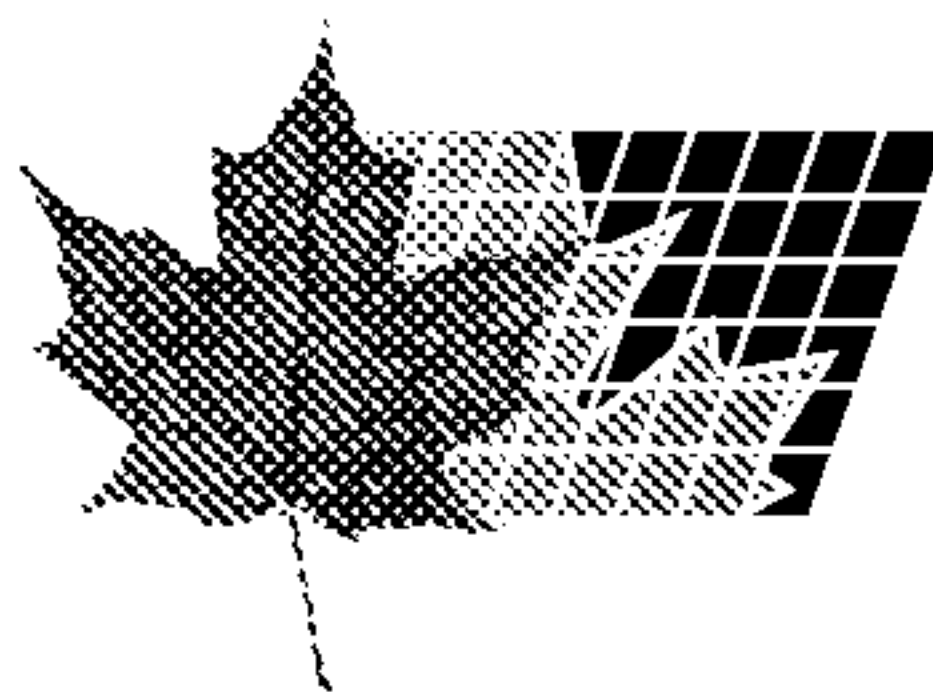
(54) **APPAREIL ET PROCEDE DE MESURE EN SIMULTANE DES
CHANGEMENTS DE DEBIT MASSIQUE ET DE FLUX
THERMIQUE**

(54) **APPARATUS AND METHOD FOR SIMULTANEOUS MEASUREMENT OF MASS AND HEAT FLOW CHANGES**



(57) L'invention concerne un appareil de mesure de débit massique et de flux thermique comprenant des microrésonateurs d'échantillon et de référence, tels que des microbalances (70, 80) à quartz d'échantillon et de référence; des capteurs (75, 85) de flux thermique d'échantillon et de référence, tel que des calorimètres de

(57) Provided is a mass and heat flow measurement apparatus comprising sample and reference microresonators (70, 80), such as sample and reference quartz crystal microbalances; sample and reference heat flow sensors (75, 85), such as sample and reference isothermal heat conduction calorimeters; and sample and



conduction thermique isothermes d'échantillon et de référence; et des puits thermiques d'échantillon et de référence couplés thermiquement aux capteurs de flux thermique. L'appareil peut être utilisé pour mesurer des changements de masse dus à la présence d'un échantillon (8) sur une surface du microrésonateur d'échantillon, et également pour mesurer les flux thermiques en provenance de l'échantillon (8) sur la surface du microrésonateur d'échantillon au moyen de capteurs de flux thermique thermiquement couplés aux microrésonateurs d'échantillon et de référence correspondants. L'invention concerne également des procédés de mesure de la masse d'un échantillon (8) et du flux thermique entre l'échantillon (8) et le puits thermique au moyen d'un tel appareil.

reference heat sinks coupled thermally to the heat flow sensors. The apparatus may be used to measure changes in mass due to sample (8) on a surface of the sample microresonator and also to measure heat flows from the sample (8) on the surface of the sample microresonator by utilizing the heat flow sensors, which are coupled thermally to the corresponding sample or reference microresonators. Also provided is a method for measuring the mass of a sample (8) and the flow of heat from the sample (8) to the heat sink by utilizing such apparatus.

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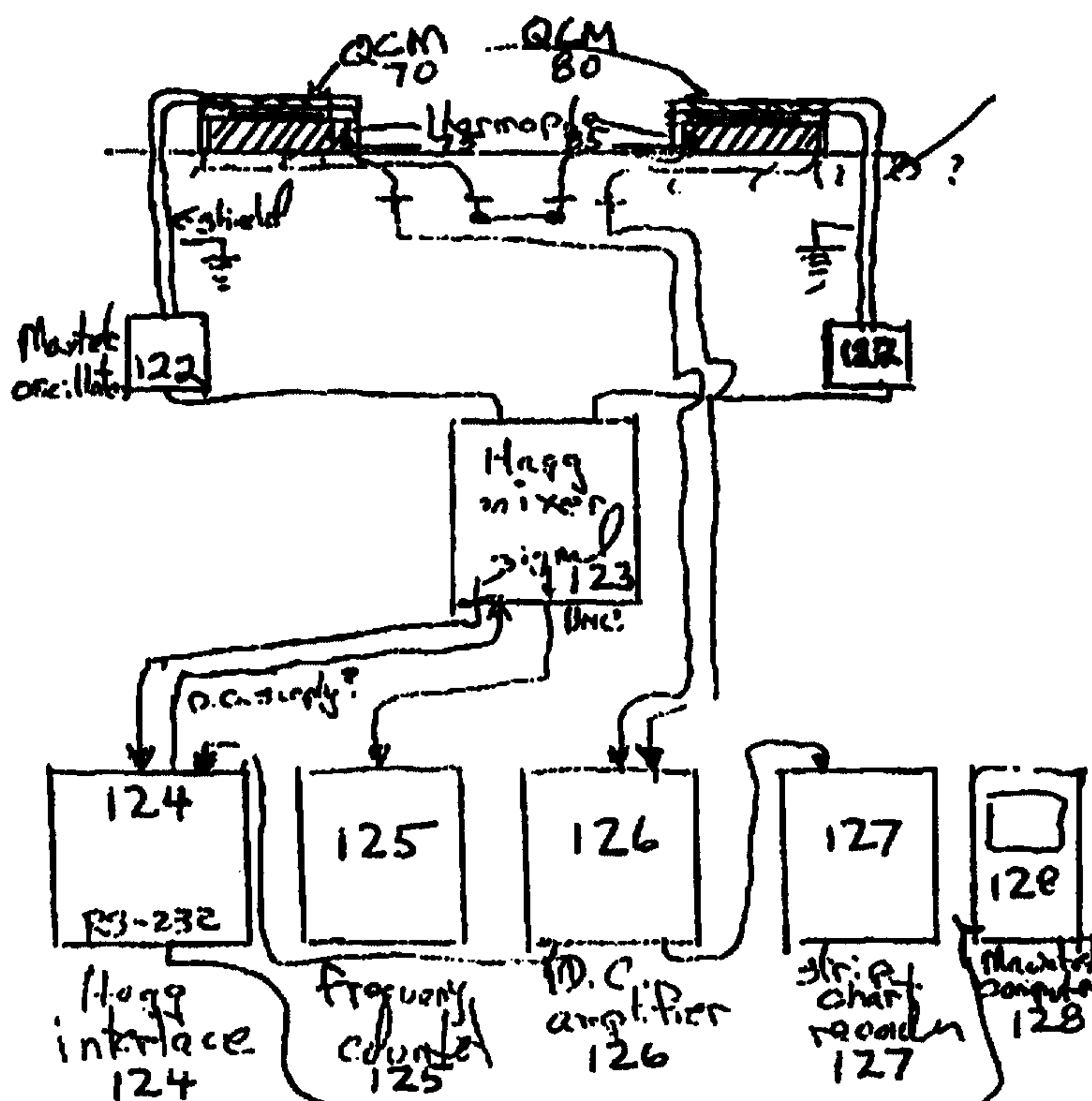
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(21) International Application Number: PCT/US98/25637 (22) International Filing Date: 2 December 1998 (02.12.98) (30) Priority Data: 60/067,239 2 December 1997 (02.12.97) US (71)(72) Applicants and Inventors: SMITH, Allan, L. [US/US]; 328 Pembroke Road, Bala Cynwyd, PA 19004 (US). WADSO, Ingemar [SE/SE]; Blackhornsvagen 6, S-224 67 Lund (SE). (74) Agents: CARLSON, Steven, A. et al.; Sampson & Associates, P.C., Suite 519, 50 Congress Street, Boston, MA 02109 (US).	(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, HR, HU, ID, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i> <i>Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>	

(54) Title: APPARATUS AND METHOD FOR SIMULTANEOUS MEASUREMENT OF MASS AND HEAT FLOW CHANGES

(57) Abstract

Provided is a mass and heat flow measurement apparatus comprising sample and reference microresonators, such as sample and reference quartz crystal microbalances (70, 80), sample and reference heat flow sensors (75, 85), such as sample and reference isothermal heat conduction calorimeters; and sample and reference heat sinks coupled thermally to the heat flow sensors. The apparatus may be used to measure changes in mass due to sample (8) on a surface of the microresonator and also to measure heat flows from the sample (8) on the surface of the sample microresonator by utilizing the heat flow sensors, which are coupled thermally to the corresponding sample or reference microresonators. Also provided is a method for measuring the mass of a sample (8) and the flow of heat from the sample (8) to the heat sink by utilizing such apparatus.



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APPARATUS AND METHOD FOR SIMULTANEOUS MEASUREMENT OF MASS AND HEAT FLOW CHANGES

RELATED APPLICATION

This application claims priority to U.S. Provisional Patent Application No. 60/067,239, filed December 2, 1997.

FIELD OF THE INVENTION

The present invention pertains generally to the field of sensors for the measurement of changes in mass and heat flow. More particularly, the present invention pertains to multiple microresonator mass and heat flow sensors which may provide simultaneous and continuous measurement of the changes in mass and heat flow at a gas-solid interface. The present invention also pertains to an apparatus comprising such sensors as sample and reference sensors, and to methods of measuring the mass and heat flow of a gas, liquid, or solid sample by utilizing such apparatus.

BACKGROUND OF THE INVENTION

Although the piezoelectric effect has been known since the 19th century, the development of quartz crystal devices which oscillate at precisely defined resonant frequencies and which can be incorporated as passive elements into electronic instruments began in the 1920's. Like much of our modern electronic technology, their development received a massive push during World War II, when over 30 million quartz crystal oscillators were produced for use in military communications equipment. Today there is widespread use of quartz crystal oscillators and of new types of microresonators in electronics wherever precise control of frequency is needed as, for example, in radio frequency communications, in frequency meters and timepieces, in scientific instrumentation, and in computers and cellular telephones.

There are several useful books which describe the physics of quartz crystal oscillators and other microresonators and their use in electronic circuits. For example, *Introduction to Quartz Crystal Unit Design* by Bottom, Van Nostrand Reinhold, New York, 1982, discusses the physical crystallography of quartz, mechanic vibrations and stress/strain relationships, the piezoelectric effect, the equivalent circuit of the quartz resonator and its use as a circuit component, the temperature stability of quartz oscillators, and other topics of importance in the application of these devices. *Science*, Vol. 249, pages 1000-1007 (1990), by Ward *et al.*, describes the converse piezoelectric effect and its use in in-situ interfacial mass detection, such as in thickness monitors for thin-film preparation and in chemical sensors for trace gases. *Analytical Chemistry*, Vol. 65, pages 940A-948A and 987A-996A (1993), by Grate *et al.*, compares the acoustical and electrical properties of five acoustic wave devices used as microsensors and transducers, including quartz crystal oscillators.

Any crystalline solid can undergo mechanical vibrations with minimum energy input at a series of resonant frequencies, determined by the shape and size of the crystal and by its elastic constants. In quartz, such vibrations can be induced by the application of a radio frequency voltage at the mechanical resonant frequency across electrodes attached to the crystal. This is termed the inverse piezoelectric effect. The thickness shear mode is the most common mechanical vibration used in quartz crystal oscillators. A typical commercially available quartz crystal oscillator is a thin circular quartz plate, cut from a single crystal at an angle of 37.25° with respect to the crystal's z axis (the so-called "AT cut"). This angle is chosen so that the temperature coefficient of the change in frequency is, to the first approximation, zero at 25°C , thus minimizing the drift in resonant frequency with ambient temperature change. A slight change in the cut angle produces crystals with zero temperature coefficients at elevated temperatures. The AT-cut plate has thin film electrodes on most of the top and bottom surfaces of the crystal, and is supported in various ways at its circumference or perimeter. Both the fundamental and the first few overtones of the thickness shear mode have been utilized in crystal oscillators. A typical

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AT-cut quartz disk piezoid operating at a 10.8 MHz fundamental has the following dimensions, according to page 99 of the above-mentioned reference by Bottom:

diameter: 8.0 mm
 electrode diameter: 2.5 mm
 5 blank thickness: 0.154 mm

The quality factor, Q, defined for any resonant circuit incorporating quartz crystal oscillators is usually not less than 10^5 and may be as high as 10^7 . With careful attention to the control of temperature in a vacuum environment, a short-term frequency stability of one part in 10^{10} can be obtained, although the stated short-term stability for commercial
 10 units is ± 3 ppm.

The resonant frequency of a quartz crystal oscillator is inversely proportional to the thickness, e, of the plate. For a circular disk,

$$f = nK/e$$

15 where $n = 1, 3, 5, \dots$ and K is the frequency constant (for example, see page 134ff of the above-mentioned reference by Bottom). For an AT-cut disk, $K = 1664$ kHz mm, so that a disk of a thickness of 1 mm will oscillate at 1.664 MHz. If this thickness is increased by the deposition of material on the surface of the quartz crystal oscillator, then its frequency will decrease.

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In 1957, Sauerbrey in *Z. Physik*, Vol. 155, 206 (1959), derived the fractional decrease in frequency f of a circular disk quartz crystal oscillator upon deposition of a mass, m, of material on its surface. The derivation relies on the assumption that a deposited foreign material exists entirely at the anti-node of the standing wave propagating
 25 across the thickness of the quartz crystal, so that the foreign deposit can be treated as an extension of the crystal, as, for example, described in *Applications of Piezoelectric Quartz Crystal Microbalances* by Lu *et al.*, Elsevier, New York, 1984. Sauerbrey's result for the fundamental vibrational mode is as follows:

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$$\Delta f/f_0 = -\Delta e/e_0 = -2f_0 \Delta m/A \sqrt{\rho \mu}$$

Here, Δe is the change in the original thickness e_0 , A is the piezoelectrically active area, ρ is the density of quartz, and μ is the shear modulus of quartz. By measuring the decrease in frequency, one thus can determine the mass of material deposited on the crystal. This is the principle of the quartz crystal microbalance. In practice, the assumptions underlying the Sauerbrey equation are valid for deposits up to about 10% of the crystal mass, although the sensitivity to mass has been shown experimentally to decrease from the center of the electrode to its edge.

Torres *et al.* in *J. Chem. Ed.*, Vol. 72, pages 67-70 (1995), describe the use of a quartz crystal microbalance to measure the mass effusing from Knudsen effusion cells at varying temperatures, in order to determine the enthalpies of sublimation. They reported a sensitivity of about 10^{-8} g/sec in the mass deposition rate. The application of the quartz crystal microbalance in chemistry for the sensitive detection of gases adsorbed on solid absorbing surfaces has been reviewed by Alder *et al.*, in *Analyst*, Vol. 108, pages 1169-1189 (1983) and by McCallum in *Analyst*, Vol. 114, pages 1173-1189 (1989). The quartz crystal microbalance principle has been applied to the development of thickness monitors in the production of thin films by vacuum evaporation, as, for example, described in the above-mentioned reference by Lu *et al.* Quartz crystal oscillators of various sizes and modes of vibration are commonly used currently in research efforts in sensor development.

Throughout this application, various publications and patents are referred to by an identifying citation. The disclosures of the publications and patents referenced in this application are hereby incorporated by reference into the present disclosure to more fully describe the state of the art to which this invention pertains.

U.S. Pat. No. 5,339,051 to Koehler *et al.* describes resonator-oscillators for use as sensors in a variety of applications. U.S. Pat. Nos. 4,596,697 to Ballato and 5,151,110 to Bein *et al.* describe coated resonators for use as chemical sensors.

To overcome the influences of temperature changes on the microresonators, U.S. Pat. Nos. 4,561,286 to Sekler *et al.* and 5,476,002 to Bower *et al.* describe active temperature control or the use of temperature sensors with the microresonators. U.S. Pat. No. 5,686,779 to Vig describes a microresonator for direct use as a thermal sensor.

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Microresonators, including quartz crystal microbalances (QCM's), have been utilized to determine the mass changes with a variety of liquid samples such as, for example, described in U.S. Pat. No. 4,788,466 to Paul *et al.* When the microresonator is coated, chemicals present in the liquid samples may be detected as, for example, described in U.S. Pat. No. 5,306,644 to Myerholtz *et al.*

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Microresonators have been adapted to measure the viscosity of a liquid sample as, for example, described in U.S. Pat. No. 4,741,200 to Hammerle. U.S. Pat. No. 5,201,215 to Granstaff *et al.* describes the use of microresonators to measure the mass of a solid and physical properties of a fluid in a sample.

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Calorimeters for various types of heat measurements are well known as, for example, described in U.S. Pat. Nos. 4,492,480 to Wadsö *et al.*; 5,295,745 to Cassettari *et al.*; and 5,312,587 to Templer *et al.* A combined scientific apparatus of a thermal analyzer, such as a calorimeter, and an X-ray diffractometer for observing simultaneously both thermodynamic and structural properties of materials is described in U.S. Pat. No. 4,821,303 to Fawcett *et al.*

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Despite the various approaches proposed for the design of sensors and measurement systems based on microresonators as the sampling device, there remains a need for sensors and measurement systems which can simultaneously and continuously measure with high sensitivity and accuracy both mass and heat flow changes of a sample in contact with the microresonator.

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SUMMARY OF THE INVENTION

One aspect of the present invention pertains to a new scientific apparatus based on the combination of two or more devices, wherein each device comprises (i) a microresonator mass sensor or microbalance, such as, for example, a quartz crystal microbalance (QCM), which may be used to measure very small changes of mass at its surface; and, (ii) a heat flow sensor, such as, for example, an isothermal heat conduction calorimeter (HCC), which may be used to measure small heat flows; and wherein at least one combined microresonator and heat flow sensor device is utilized as a reference device and at least one combined microresonator and heat flow sensor device is utilized as a sample device to measure the sample. In one embodiment, the dual microresonator and heat flow sensor sample and reference apparatus measures simultaneously and continuously, with high sensitivity (nanogram in mass, sub-microwatt in heat flow), the changes in mass and heat flow at a small gas-solid interface, for example, about 1 cm² or less in area, due to chemical processes such as evaporation or condensation, adsorption or desorption, or gas-surface reactions. The new scientific apparatus of the present invention may be advantageously utilized in a variety of applications such as, for example, studying the hydration and dehydration of films of proteins and other biomolecules deposited on solid substrates, particularly for films utilized in biosensors, diagnostic immunoassays, the separation of proteins by chromatography, and as models for biological and biocompatible membranes and surfaces; studying the energetics of intermolecular interactions at the surface of polymer films and other organic surfaces important in adhesion, lubrication, wetting, and corrosion; and studying the energetics of the drying and curing of both water-based and organic solvent-based paints and finishes.

One aspect of the present invention pertains to a mass and heat flow measurement apparatus comprising (i) a sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to the first heat flow sensor, wherein the first heat flow sensor is thermally coupled to the first microresonator; and further wherein

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the first microresonator is capable of measuring the mass of a sample in contact with the first microresonator, and the first heat flow sensor is capable of measuring the flow of heat from the sample to the heat sink; (ii) a reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to the second microresonator, and a heat sink coupled thermally to the second heat flow sensor; and, (iii) a chamber housing the sample and reference sensors, wherein the reference sensor is isolated from the sample; and further wherein the second microresonator is capable of measuring a reference signal relating to mass at a surface of the second microresonator, and the second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of the second microresonator to the heat sink coupled thermally to the second heat flow sensor. In one embodiment, the first microresonator comprises a piezoelectric substrate having a perimeter, a first face for directly contacting the sample, and a second opposite face isolated from contacting the sample; and further wherein the second microresonator comprises a piezoelectric substrate having a perimeter, a first face, and a second opposite face, the piezoelectric substrates of the first and second microresonators having a resonant frequency and capable of providing a measurement signal based on the resonant frequency. In one embodiment, the sample is a solid sample.

Suitable microresonators for the apparatus of this invention include, but are not limited to, bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the first and second microresonators of the apparatus of the present invention are quartz crystal microbalances. In one embodiment, the first microresonator comprises a surface coating with an affinity for at least one component of the sample. In one embodiment, the second microresonator comprises a surface coating with an affinity for at least one component of the sample.

In one embodiment, the first and second heat flow sensors of the apparatus of this invention comprise a thermopile.

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Another aspect of the present invention pertains to a mass and heat flow measurement system comprising (i) at least one mass and heat flow measurement sample sensor comprising a microresonator, a heat flow sensor coupled thermally to the microresonator, and a heat sink coupled thermally to the heat flow sensor, wherein the microresonator generates data relating to the changes in mass on a surface of the microresonator arising from contacting the microresonator with a sample; and further wherein the heat flow sensor generates data relating to the changes in flow of heat from the sample to the heat sink from contacting the microresonator with the sample; (ii) at least one mass and heat flow measurement reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to the reference microresonator, and a heat sink coupled thermally to the reference heat flow sensor, wherein the microresonator of the reference sensor is not in contact with the sample; and further wherein the reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator, and the reference heat flow sensor generates data relating to the changes in flow of heat from the surface of the reference microresonator to the heat sink coupled thermally to the reference heat flow sensor; and, (iii) a measurement instrument capable of correlating the data from the sample and reference sensors so as to provide measurement of the mass of the sample and the flow of heat from the sample to the heat sink coupled thermally to the heat flow sensor of the sample sensor. In one embodiment of the system of this invention, the microresonator of the sample sensor comprises a piezoelectric substrate having a perimeter, a first face for directly contacting a sample, and a second opposite face isolated from contacting the sample; and further wherein the reference microresonator comprises a piezoelectric substrate having a perimeter, a first face, and a second opposite face, the piezoelectric substrates of the microresonator of the sample sensor and the reference microresonator having a resonant frequency and capable of providing a measurement signal based on the resonant frequency. In one embodiment, the sample is a solid sample.

Suitable microresonators for the sample sensor and suitable reference microresonators for the system of the present invention include, but are not limited to,

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bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the microresonator of the sample sensor and the reference microresonator are quartz crystal microbalances. In one embodiment, the microresonator of the sample sensor
5 comprises a surface coating with an affinity for at least one component of the sample. In one embodiment, the reference microresonator comprises a surface coating with an affinity for at least one component of the sample.

In one embodiment, the heat flow sensor of the sample sensor and the reference
10 heat flow sensor of the system of the present invention comprise a thermopile.

Another aspect of the present invention pertains to a method for measuring the mass of a sample and the flow of heat from the sample to a heat sink, which method comprises the steps of: (i) contacting the sample with a mass and heat flow measurement
15 system, as described herein; (ii) obtaining data from both the sample and reference sensors of the mass and heat flow measurement system of the present invention; and, (iii) determining the mass of the sample and the flow of heat from the sample to the heat sink coupled thermally to the heat flow sensor of the sample sensor. In one embodiment, the sample is a solid sample, and, preferably, the method of this invention measures the
20 enthalpy of sublimation of the solid sample.

Still another aspect of the present invention pertains to a mass and heat flow measurement apparatus comprising (i) a gas sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to the first heat
25 flow sensor, wherein the first heat flow sensor is thermally coupled to the first microresonator; and further wherein the first microresonator comprises a coated surface and is capable of measuring the changes in mass when a gas reacts with, is adsorbed, or is desorbed from the coated surface; and the first heat flow sensor is capable of measuring the flow of heat from the coated surface to the heat sink; (ii) a gas reference sensor
30 comprising a second microresonator, a second heat flow sensor coupled thermally to the

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second microresonator, and a heat sink coupled thermally to the second heat flow sensor; and, (iii) a chamber housing the gas sample and gas reference sensors, wherein the gas reference sensor is isolated from the gas in contact with the first microresonator; and further wherein the second microresonator is capable of measuring a reference signal relating to mass at a surface of the second microresonator, and the second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of the second microresonator to the heat sink coupled thermally to the second heat flow sensor. In one embodiment, the chamber further comprises a gas input lead for introducing the gas into contact to the coated surface of the first microresonator and a gas output lead for removing the gas from contact to the coated surface of the first microresonator.

Yet another aspect of the present invention pertains to a mass and heat flow measurement system comprising (i) at least one mass and heat flow measurement gas sample sensor comprising a microresonator, a heat flow sensor coupled thermally to the microresonator, and a heat sink coupled thermally to the heat flow sensor, wherein the microresonator comprises a coated surface and generates data relating to the changes in mass on the coated surface of the microresonator arising from contacting the coated surface with a gas; and further wherein the heat flow sensor generates data relating to the changes in flow of heat from the coated surface to the heat sink from contacting the coated surface with the gas; (ii) at least one mass and heat flow measurement gas reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to the reference microresonator, and a heat sink coupled thermally to the reference heat flow sensor, wherein the microresonator of the gas reference sensor is not in contact with the gas in contact with the microresonator of the gas sample sensor; and further wherein the reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator, and the reference heat flow sensor generates data relating to the changes in flow of heat from the surface of the reference microresonator to the heat sink coupled thermally to the reference heat flow sensor; and, (iii) a measurement instrument capable of correlating the data from the gas sample and gas

reference sensors so as to provide measurement of the changes in mass on the coated surface of the microresonator of the gas sample sensor and the flow of heat from the coated surface to the heat sink coupled thermally to the heat flow sensor of the gas sample sensor. In one embodiment, the system further comprises a gas input lead for introducing the gas into contact to the coated surface of the microresonator of the gas sample sensor and a gas output lead for removing the gas from contact to the coated surface of the microresonator of the gas sample sensor.

Another aspect of the present invention pertains to a method for measuring the change in mass and flow of heat from a coated surface to a heat sink when a gas reacts with, is adsorbed, or is desorbed from the coated surface, which method comprises the steps of: (i) contacting the gas with a mass and heat flow gas measurement system, as described herein; (ii) obtaining data from both the gas sample and gas reference sensors of the mass and heat flow gas measurement system of this invention; and, (iii) determining the changes in mass and the flow of heat from the coated surface of the microresonator of the gas sample sensor to the heat sink coupled thermally to the heat flow sensor of the gas sample sensor, which changes arise when the gas reacts with, is adsorbed, or is desorbed from the coated surface. In one embodiment of the method, the mass and heat flow gas measurement system further comprises a gas input lead for introducing the gas to the microresonator of the gas sample sensor and a gas output lead for removing the gas from contact to the microresonator of the gas sample sensor. In one embodiment, the method measures the molar heat of adsorption of the gas, and, preferably, the molar heat of adsorption is measured in real time. In one embodiment, the reference microresonator comprises a coated surface. In one embodiment, the coated surface of the reference microresonator comprises the same coating as the coated surface of the microresonator of the gas sample sensor. In one embodiment, the method measures the molar heat of reaction of the gas with the coated surface, and, preferably, the molar heat of reaction is measured in real time. In one embodiment, the method measures the molar heat of desorption of the gas, and, preferably, the molar heat of desorption is measured in real time. In one embodiment, the microresonator of the gas sample sensor and the reference

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microresonator are selected from the group of microresonators consisting of: bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the microresonator of the gas sample sensor and the reference microresonator are quartz
5 crystal microbalances.

Another aspect of the present invention pertains to a heat flow measurement apparatus comprising (i) a liquid sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to the first heat flow sensor, wherein
10 the first heat flow sensor is thermally coupled to the first microresonator; and further wherein the first microresonator is capable of measuring a signal relating to mass at a surface of the first microresonator, and the first heat flow sensor is capable of measuring the flow of heat from a liquid sample disposed on the first microresonator to the heat sink;
(ii) a liquid reference sensor comprising a second microresonator, a second heat flow
15 sensor coupled thermally to the second microresonator, and a heat sink coupled thermally to the second heat flow sensor; and, (iii) a chamber housing the liquid sample and liquid reference sensors, wherein the liquid reference sensor is isolated from the liquid sample in contact with the first microresonator; and further wherein the second microresonator is capable of measuring a reference signal relating to mass at a surface of the second
20 microresonator, and the second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of the second microresonator to the heat sink coupled thermally to the second heat flow sensor. In one embodiment of the heat flow apparatus of this invention, the chamber further comprises a liquid input lead for introducing the liquid sample into contact to the first microresonator. In one embodiment,
25 the first microresonator is capable of measuring the mass of the liquid sample in contact with the first microresonator.

Still another aspect of this invention pertains to a heat flow measurement system comprising (i) at least one heat flow measurement liquid sample sensor comprising a
30 microresonator, a heat flow sensor coupled thermally to the microresonator, and a heat

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sink coupled thermally to the heat flow sensor, wherein the microresonator is capable of measuring a signal relating to mass at a surface of the microresonator; and further wherein the heat flow sensor generates data relating to the changes in the flow of heat from a liquid sample to the heat sink from contacting the microresonator with the liquid sample; (ii) at
5 least one heat flow measurement liquid reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to the reference microresonator, and a heat sink coupled thermally to the reference heat flow sensor, wherein the microresonator of the reference sensor is not in contact with the liquid sample in contact with the microresonator of the liquid sample sensor; and further wherein the
10 reference microresonator is capable of measuring a reference signal relating to mass at a surface of the reference microresonator, and the reference heat flow sensor generates data relating to the changes in flow of heat from the surface of the reference microresonator to the heat sink coupled thermally to the reference heat flow sensor; and, (iii) a measurement instrument capable of correlating the data from the liquid sample and liquid reference
15 sensors so as to provide measurement of the flow of heat from the liquid sample to the heat sink coupled thermally to the heat flow sensor of the liquid sample sensor. In one embodiment of the heat flow measurement system of the present invention, the system further comprises a liquid input lead for introducing the liquid sample to the microresonator of the liquid sample sensor. In one embodiment, the microresonator of the
20 liquid sample sensor generates data relating to the changes in mass on a surface of the microresonator of the liquid sample sensor, which data arises from contacting the microresonator of the liquid sample sensor with the liquid sample; wherein the reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator; and further wherein the measurement instrument is capable of correlating
25 the data from the liquid sample and liquid reference sensors so as to further provide measurement of the mass of the liquid sample. In one embodiment, the mass of the liquid sample is known.

Another aspect of the present invention pertains to a method for measuring the
30 change in the flow of heat from a liquid sample to a heat sink, which method comprises

the steps of: (i) contacting the liquid sample with a heat flow measurement system, as described herein; (ii) obtaining data from both the liquid sample and liquid reference sensors of the heat flow measurement system of this invention; and, (iii) determining the flow of heat from the liquid sample to the heat sink coupled thermally to the heat flow sensor of the liquid sample sensor. In one embodiment, the heat flow measurement system further comprises a liquid input lead for introducing the liquid sample to the microresonator of the liquid sample sensor. In one embodiment, the microresonator of the liquid sample sensor generates data relating to the changes in mass on a surface of the microresonator of the liquid sample sensor, which data arises from contacting the microresonator of the liquid sample sensor with the liquid sample; wherein the reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator; and further wherein the measurement instrument is capable of correlating the data from the liquid sample and liquid reference sensors so as to further provide measurement of the mass of the liquid sample. In one embodiment, the mass of the liquid sample is known. In one embodiment, the method measures the molar heat of evaporation of the liquid sample. In one embodiment, the microresonator of the liquid sample sensor comprises a coated surface, and, preferably, the reference microresonator also comprises a coated surface, and, most preferably, the coated surface of the reference microresonator comprises the same coating as the coated surface of the microresonator of the liquid sample sensor. In one embodiment, the microresonator of the liquid sample sensor and the reference microresonator are selected from the group of microresonators consisting of: bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the microresonator of the liquid sample sensor and the reference microresonator are quartz crystal microbalances.

As one skilled in the art will appreciate, features of one embodiment and aspect of the invention are applicable to other embodiments and aspects of the invention.

BRIEF DESCRIPTION OF THE DRAWINGS

The foregoing summary, as well as the following detailed description of
embodiments of the invention, will be better understood when read in conjunction with the
5 appended drawings. For the purpose of illustrating the invention, particular arrangements
and methodologies are shown in the drawings. It should be understood, however, that the
invention is not limited to the precise arrangements shown or to the methodologies of the
detailed description.

10 Figure 1 illustrates the contrast between the functionality of an adiabatic
calorimeter versus a heat conduction calorimeter.

Figure 2 shows the basic equations for heat conduction calorimetry.

15 Figure 3 shows a schematic representation of a typical thermoelectric thermopile
module.

Figure 4 shows a schematic representation of a quartz crystal microbalance and
heat flow sensor combination device.

20 Figure 5 shows a schematic representation of one embodiment of the multiple
quartz crystal microbalance and heat flow sensor combination devices in accordance with
one embodiment of the present invention.

25 Figure 6 shows a block diagram schematic of the electronics of the devices shown
in Figure 5.

Figure 7 shows a graphical representation of the response of the devices of Figure
5 upon deposition of a drop of decane.

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Figure 8 shows a graphical representation of the calibration of the devices of Figure 5 utilizing a helium-neon (He-Ne) laser.

Figure 9 shows a graphical representation of the heat generated by the devices of Figure 5 upon the application of 5.0 MHz rf power.

Figure 10 shows a graphical representation of the heat flow and mass change signals of the devices shown in Figure 5 upon the deposition of 20 mg of hexane on the surface of the quartz crystal microbalance in the left quartz crystal microbalance and heat flow sensor combination device.

Figure 11 shows a graphical representation of the heat flow and mass change signals of the devices shown in Figure 5 upon the deposition of 20 mg of hexane on the surface of the quartz crystal microbalance in the right quartz crystal microbalance and heat flow sensor combination device.

Figure 12 shows a graphical representation of a quartz crystal microbalance output upon the introduction of organic vapors.

Figure 13 shows diagrammatic representations of traces from the quartz crystal microbalance in the devices of Figure 5 in response to the deposition of several organic vapors on the surface of one of the quartz crystal microbalances.

Figure 14 shows diagrammatic representations of traces from both heat flow sensors in the devices of Figure 5 in response to the deposition of several organic vapors on the surface of one of the quartz crystal microbalances.

Figure 15 shows diagrammatic representations for the quartz crystal microbalances in the devices of Figure 5 in response to the deposition of toluene vapor on the surface of one of the quartz crystal microbalances.

Figure 16 shows diagrammatic representations for the heat flow sensors in the devices of Figure 5 in response to the deposition of toluene vapor on the surface of one of the quartz crystal microbalances.

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Figure 17 shows diagrammatic representations for the quartz crystal microbalances in the devices of Figure 5 in response to the deposition of chloroform vapor on the surface of one of the quartz crystal microbalances.

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Figure 18 shows diagrammatic representations for the heat flow sensors in the devices of Figure 5 in response to the deposition of chloroform vapor on the surface of one of the quartz crystal microbalances.

Figure 19 shows diagrammatic representations for the quartz crystal microbalances in the devices of Figure 5 in response to the deposition of n-butanol vapor on the surface of one of the quartz crystal microbalances.

Figure 20 shows diagrammatic representations for the heat flow sensors in the devices of Figure 5 in response to the deposition of n-butanol vapor on the surface of one of the quartz crystal microbalances.

DETAILED DESCRIPTION OF THE INVENTION

The combined microresonator and heat flow sensor sample and reference devices of the present invention provide a new apparatus and method in thermal analysis and calorimetry. This new apparatus and method provide the capability of measuring the change in heat flow and mass at a gas-solid interface as the compositions of both the gas phase and the solid surface change. In thermodynamic terms, the combined microresonator and heat flow sensor sample and reference devices are capable of measuring directly the partial molal enthalpy of a volatile component, i , of a film on a

surface, as the other non-volatile components and the temperature (T) and pressure (P) are held constant:

$$H_i = (\partial H) / \partial n_i \big|_{T,P,n_j}$$

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where j is the number of moles of the total components (n).

The contrast between adiabatic calorimetry and heat conduction calorimetry is illustrated in Figure 1. For adiabatic calorimetry, the temperature (T) vs. time is measured in an adiabatic vessel of known heat capacity (C) to provide the heat (Q). For heat
10 conduction calorimetry, the thermal power vs. time (t) is measured in a vessel in which the heat (Q) generated by the chemical process flows through a heat flow sensor. The basic equations for heat conduction calorimetry or "Calvet calorimetry" are shown in Figure 2, where P is the thermal power in watts, S is the thermopile sensitivity in volts/watt, U is the
15 thermopile voltage in volts, and τ is the time constant of the calorimeter in seconds. At steady state, $U = SP$. The time constant is determined by C/G , where C is the heat capacity of the reaction vessel and G is the thermal conductance of the thermopile. The sensing element in a heat flow sensor, such as a heat conduction calorimeter, is typically a thermopile, or thermoelectric, module. Examples of these thermopile modules are
20 manufactured by Melcor, Inc., of Trenton, New Jersey, and are widely used as thermoelectric heat pumps in computers and other electronics. Figure 3 shows some design details of a typical thermoelectric thermopile, as, for example, those made by Melcor, Inc. The top layer 1 of the assembly is a cold junction where heat is absorbed. The electrical insulator layer 2 and electrical conductor layer 3 are on both sides of
25 bismuth telluride elements 4 with "N" and "P" type properties. The bottom layer 5 of the assembly is a hot junction where heat is rejected. The elements are electrically connected in series through a direct current (dc) source and are thermally in parallel. In practical use, couples are combined in a module where they are connected electrically in series, and thermally in parallel. Normally a module is the smallest component commercially
30 available. Modules are available in a great variety of sizes, shapes, operating currents, operating voltages, and ranges of heat pumping capacity.

Mass and Heat Flow Measurement Apparatus and System

A schematic diagram of one aspect of the microresonator and heat flow sensor combination device is shown in Figure 4. This sensor combination device is combined with at least one additional sensor combination device to provide the combined microresonator and heat flow sensor sample and reference devices in the novel apparatus and method of the present invention. As illustrated in Figure 4, a circular disk, (a), of an AT-cut quartz crystal of diameter, D_q , and thickness, w , is mounted with its circumferential edge or perimeter in good thermal contact to a metallic cylinder 6 with a bottom plate 7. The disk has electrodes (b) of diameter, D_e , deposited on both faces. The bottom plate is in contact to a thermopile (c), which is in turn in contact to a heat sink (d), for example, the bottom of a can which is thermostated in a constant temperature bath. Thus, the heat flow sensor comprising the thermopile is coupled thermally to the microresonator, and the heat sink is coupled thermally to the heat flow sensor. On the top surface or first face of the quartz crystal oscillator with electrode is deposited a sample 8 in a circular area of diameter, d . It is this sample which will produce a heat flow rate, ϕ (watts), when, for example, subliming, adsorbing, desorbing, or reacting at a rate of dn/dt moles per second, where the symbol, ΔH_{sub} , is used to represent the molar enthalpy change of any of the processes mentioned above and $\phi = \Delta H_{sub} dn/dt$. For example, a typical sublimation enthalpy of 50 kJ mol^{-1} , combined with a heat flow rate of 100 nW typical of the baseline noise in a good heat conduction microcalorimeter, corresponds to a sublimation rate, dn/dt , of $5.0 \times 10^{-12} \text{ mole sec}^{-1}$. For a substance of molar mass of 200 g mol^{-1} , this corresponds to a mass loss of 1.0 ng sec^{-1} . The Nanowatt Amplifier available from Thermometric AB in Sweden, as described in *Thermometric Calorimeter News*, February 1997, page 3, with a noise level for an empty ampoule heat conduction calorimeter of 2 nW, will increase this sensitivity by a factor of 50, or to $1.0 \times 10^{-13} \text{ mole sec}^{-1}$ (20 pg sec^{-1}). The bottom surface or opposite face of the quartz crystal with electrodes is isolated from contacting the sample.

A key requirement in the microresonator and heat flow sensor combination device is to provide a path of high thermal conductivity from the piezoelectric crystal surface to the heat flow sensor. Otherwise, at high heat flow rates, the central portion of the piezoelectric crystal surface may heat up, thus producing temperature gradients within the crystal and accompanying shifts in resonant frequency. There must be good thermal contact between the piezoelectric crystal and the mounting of the thermally conductive material, so the details of mechanical support are important. In Chapter 10 of the above-mentioned reference by Bottom, it is shown that the quartz between the two circular deposited electrodes is the region undergoing transverse shear waves, and that the surrounding bare quartz annulus serves to damp higher acoustic modes. To the first approximation, the annulus functions as an acoustical node. It is therefore available to mount the crystal and make a path of high thermal conductivity between the piezoelectric substrate and the heat flow sensor without affecting the high quality factor, Q , of acoustical vibrations at resonance. Figure 4 shows one possible mounting arrangement of the microresonator and heat flow sensor combination device. The heat conductive material providing the high thermal conductivity between the piezoelectric substrate and the heat flow sensor is not in contact with the acoustically active region undergoing transverse shear waves, including the acoustically active region on the opposite face of the piezoelectric crystal.

It is possible to estimate the temperature gradient in the quartz between the two electrodes under operating conditions for a microresonator comprising a quartz crystal. The radial temperature distribution, $T(r)$, in a disk of diameter, D_e , and thickness, c , connected to a heat sink of temperature, T_0 , at its edge and uniformly heated on its surface with an input power per unit area, P , has been derived by Ginnings *et al.*, in "Principles of Calorimetric Design" in *Experimental Thermodynamics: Calorimetry of Non-Reacting Systems*, Vol. 1, edited by McCullough *et al.*, Butterworth, London, 1968, as follows:

$$T(r) - T_0 \cong P/4\lambda e [D_e^2/4 - r^2]$$

where λ is the thermal conductivity of the disk material. Thermal conductivity in quartz is anisotropic. For heat flow along the C-axis (the optical axis), $\lambda = 11.1 \text{ W K}^{-1} \text{ m}^{-1}$, whereas for a perpendicular axis, $\lambda = 5.88 \text{ W K}^{-1} \text{ m}^{-1}$. To estimate temperature gradients, we take
5 the mean, $\lambda = 8.5 \text{ W K}^{-1} \text{ m}^{-1}$, and use the dimensions given above ($D_e = 0.0025 \text{ m}$, $e = 0.000154 \text{ m}$, or electrode area $= 4.91 \times 10^{-6} \text{ m}^2$). Assuming a heat flow of $100 \mu\text{W}$, or 10^3 times the noise level of the microcalorimeter, the temperature difference between the center of the disk and the edge of the electrode ($r = D_e$) is only $6 \times 10^{-3} \text{ K}$, independent of disk diameter. This is much too small to create spurious effects due to the dependence of
10 quartz resonant frequency on temperature. Thus, for example, quartz is an adequate thermal conductor to function in the microresonator and heat flow sensor combination of the present invention.

For the embodiment shown in Figure 4, the "reaction vessel" of the microresonator
15 and heat flow sensor of this invention has a small heat capacity and thus a short time constant, as, for example, described in *J. Biochemical and Biophysical Methods*, Vol. 28, pages 85-100 (1994), by Backman *et al.* This short time constant may perhaps be as short as a few seconds. This makes less demands on the long-term stability of both the microresonator and the heat flow sensor and the temperature stability of the heat sink.
20 The short time constant will also be useful in following the kinetics of adsorption or desorption of materials. The operating frequency of the microresonator should be high enough to assure good counting statistics in the frequency measurement, but high frequencies imply thin quartz crystals and a corresponding fragility and a decrease in thermal conductivity. The width, w , of the microresonator is a design parameter to be
25 determined by optimizing these conflicting requirements.

As shown in Figure 4, one embodiment of the microresonator and heat flow sensor combination device is a single device incorporating one microresonator, such as a quartz crystal microbalance, and one heat flow sensor comprising a thermopile for mass and heat
30 flow measurements.

Figure 5 shows one embodiment of the combined microresonator and heat flow sensor sample and reference devices of the present invention. The apparatus 30 (not to scale) includes two microresonator and heat flow sensor combination devices, one serving as a reference sensor 10 and one as a sample sensor 20 on which the sample 8 is placed. Each sensor combination device in Figure 5 has the elements as illustrated and labeled for the single combination device shown in Figure 4 and is housed in a chamber 40 containing electronics and other components. The metallic cylinder 6, which acts as a heat conductive material coupling the heat flow sensor to the microresonator, may be in a variety of designs, such as D-shaped half cylinders, and may be made of a variety of good thermal conductors, such as brass and copper.

Figure 6 shows a schematic diagram of the combined microresonator and heat flow sensor sample and reference device electronics for the apparatus of Figure 5. The sample quartz crystal microbalance 70, reference quartz crystal microbalance 80, sample thermopile 75, and reference thermopile 85 are connected electronically to provide the measurement signals through the use of an oscillator 122, a signal mixer 123, an interface 124, a frequency counter 125, a dc amplifier 126, a strip chart recorder 127, and a computer 128. The voltage from the thermopile sensors is the difference in voltage between sample and reference heat flow sensors, and the frequency from the mass measurement channel is the difference in frequency between the two microresonators.

Preliminary experiments showed that the combined microresonator and heat flow sensor apparatus, as illustrated in one embodiment in Figures 5 and 6, has a high sensitivity in both mass measurement and heat flow measurement. For example, Figure 7 shows the response of both channels when a 5 microliter drop of decane was deposited on the sample quartz crystal microbalance. The dashed line is the response of the quartz crystal microbalance channel in Hz, and the continuous line is the response of the heat flow sensor whose signal was about 1 milliwatt full scale.

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Calibration of the thermopile of the heat flow sensor is accomplished, for example, by shining a 0.95 milliwatt He-Ne laser onto each microresonator of the microresonator and heat flow sensor combination and measuring the resulting heat flow sensor voltage. Figure 8 shows an example of this calibration.

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When 5.0 MHz of radio-frequency (rf) power was supplied to the piezoelectric quartz crystal of the quartz crystal microbalance, the heat generated (about 115 microwatts) could be readily detected by the heat flow sensor. Figure 9 shows this effect.

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The expected detection limits of the heat flow and mass change measurements of the microresonator and heat flow sensor combination may be estimated. For a microresonator, such as a quartz crystal microbalance, the frequency shift, $\delta\nu$, is related to the mass change per unit area, δm , deposited on the microresonator surface by the Sauerbrey equation, which for the embodiment of a quartz crystal microbalance shown in Figure 4, can be expressed as:

15

$$\delta\nu = -57 \delta m$$

20

where the frequency shift is in Hz and the mass change is in micrograms/cm². Since the observed short-term stability of the quartz crystal microbalance is about ± 1 Hz in its present configuration, the mass detection limit is presently about 18 ng/cm². With better counting electronics, this limit could be reduced by at least an order of magnitude. The sensitivity of the heat flow sensor is about 0.3 V/W, so the observed rms noise in the heat flow sensor output channel of ± 1 microvolt corresponds to a heat conduction detection limit of 3 microwatts.

25

One aspect of the present invention pertains to a mass and heat flow measurement apparatus comprising (i) a sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to the first heat flow sensor, wherein the first heat flow sensor is thermally coupled to the first microresonator; and further wherein the first microresonator is capable of measuring the mass of a sample in contact with the first microresonator, and the first heat flow sensor is capable of measuring the flow of heat

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from the sample to the heat sink; (ii) a reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to the second microresonator, and a heat sink coupled thermally to the second heat flow sensor; and, (iii) a chamber housing the sample and reference sensors, wherein the reference sensor is isolated from the sample; and further wherein the second microresonator is capable of measuring a reference signal relating to mass at a surface of the second microresonator, and the second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of the second microresonator to the heat sink coupled thermally to the second heat flow sensor. In one embodiment, the first microresonator comprises a piezoelectric substrate having a perimeter, a first face for directly contacting the sample, and a second opposite face isolated from contacting the sample; and further wherein the second microresonator comprises a piezoelectric substrate having a perimeter, a first face, and a second opposite face, the piezoelectric substrates of the first and second microresonators having a resonant frequency and capable of providing a measurement signal based on the resonant frequency. In one embodiment, the sample is a solid sample.

A wide variety of microresonators may be utilized in the mass and heat flow measurement apparatus and systems of the present invention as, for example, the microresonators described in the afore-mentioned references by Grate *et al.*, Alder *et al.*, McCullen, and Lu *et al.* Suitable microresonators for the apparatus of this invention include, but are not limited to, bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the first and second microresonators of the apparatus of the present invention are quartz crystal microbalances. In one embodiment, the first microresonator comprises a surface coating with an affinity for at least one component of the sample. In one embodiment, the second microresonator comprises a surface coating with an affinity for at least one component of the sample.

A wide variety of heat flow sensors may be utilized in the mass and heat flow apparatus and systems of the present invention, such as, for example, the isothermal heat

conduction calorimeters described in *Chemical Society Reviews*, Volume 1997, pages 79-86 (1997) by Wadsö and references therein. In one embodiment, the first and second heat flow sensors of the apparatus of this invention comprise a thermopile.

5 Another aspect of the present invention pertains to a mass and heat flow measurement system comprising (i) at least one mass and heat flow measurement sample sensor comprising a microresonator, a heat flow sensor coupled thermally to the microresonator, and a heat sink coupled thermally to the heat flow sensor, wherein the microresonator generates data relating to the changes in mass on a surface of the
10 microresonator arising from contacting the microresonator with a sample; and further wherein the heat flow sensor generates data relating to the changes in flow of heat from the sample to the heat sink from contacting the microresonator with the sample; (ii) at least one mass and heat flow measurement reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to the reference
15 microresonator, and a heat sink coupled thermally to the reference heat flow sensor, wherein the microresonator of the reference sensor is not in contact with the sample; and further wherein the reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator, and the reference heat flow sensor generates data relating to the changes in flow of heat from the surface of the reference
20 microresonator to the heat sink coupled thermally to the reference heat flow sensor; and, (iii) a measurement instrument capable of correlating data from the sample and reference sensors so as to provide measurement of the mass of the sample and the flow of heat from the sample to the heat sink coupled thermally to the heat flow sensor of the sample sensor. In one embodiment of the system of this invention, the microresonator of the sample
25 sensor comprises a piezoelectric substrate having a perimeter, a first face for directly contacting a sample, and a second opposite face isolated from contacting the sample; and further wherein the reference microresonator comprises a piezoelectric substrate having a perimeter, a first face, and a second opposite face, the piezoelectric substrates of the microresonator of the sample sensor and the reference microresonator having a resonant

frequency and capable of providing a measurement signal based on the resonant frequency. In one embodiment, the sample is a solid sample.

Suitable microresonators for the sample sensor and suitable reference
5 microresonators for the system of the present invention include, but are not limited to, bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the microresonator of the sample sensor and the reference microresonator are quartz
10 crystal microbalances. In one embodiment, the microresonator of the sample sensor comprises a surface coating with an affinity for at least one component of the sample. In one embodiment, the reference microresonator comprises a surface coating with an affinity for at least one component of the sample.

In one embodiment, the heat flow sensor of the sample sensor and the reference
15 heat flow sensor of the system of the present invention comprise a thermopile.

To facilitate the introduction of both liquid and gaseous samples to either the sample or reference microresonator and heat flow sensor combination device, KEL-F inserts which screw into the top of the aluminum sample and reference chambers were
20 designed and constructed. In one embodiment, each insert directs three TEFLON (a trademark for polytetrafluorethylene polymer available from DuPont Corporation, Wilmington, DE) tubes of 0.6 mm i.d. into the region above the microresonator surface. For example, one tube is used to transport liquids to the surface of the microresonator, and the other two are used as gas inflow and outflow leads.

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Figures 10 and 11 show the mass and heat flow changes when 1 drop of hexane (20 mg) is deposited on the left and right quartz crystal microbalance and heat flow sensor combination devices, respectively. On the right quartz crystal microbalance and heat flow
30 sensor combination device, the strong endothermic signal from the heat flow sensor integrates to a heat of 8 J absorbed by the evaporating hexane. The corresponding mass

change cannot be detected while the quartz crystal microbalance surface is covered with liquid, because of the well-known inability of quartz crystal microbalances to measure accurately the mass of films with low viscoelasticities. However, the shift of the quartz crystal microbalance baseline (from before to after liquid deposition and evaporation) indicates that a residual deposit has been left on the approximately 1 cm² quartz crystal microbalance surface of 20 to 30 micrograms, or about 0.1% of the deposited hexane mass. Since no attempt was made to purify the hexane or to eliminate its contact with soluble organic impurities, such a shift is reasonable. It should be noted that the frequency shift is of opposite sign for the left and right quartz crystal microbalances. This is because the rf electronics detects the difference frequency between the two quartz crystal microbalances. The left quartz crystal microbalance oscillates at 5.0002×10^6 Hz and the right quartz crystal microbalance oscillates at 5.000×10^6 Hz, and the difference signal of about 2000 Hz is measured. When a deposit is placed on the left quartz crystal microbalance, its frequency decreases and the difference signal decreases. When a deposit is placed on the right quartz crystal microbalance, its frequency decreases and the difference signal increases.

Since the deposition of organic liquids on the quartz crystal microbalance, even in small amounts, gave enormous heat flow sensor signals and uninterpretable quartz crystal microbalance signals, it was decided to study the response of the gold surface of the quartz crystal microbalance to the introduction of organic vapors. The hope was that these vapors would adsorb exothermically on the gold, thereby producing a corresponding mass increase. Figure 12 shows experiments in which the top trace is the quartz crystal microbalance signal, and the bottom traces are the right and left heat flow sensor signals. At the first event, when the rf power to the two quartz crystal microbalances was turned on, both heat flow sensors responded with small exothermic signals, as expected. When the nitrogen gas was turned on and a small aliquot of methanol vapor was introduced into the flowing steam by allowing a 10 microliter drop of methanol to evaporate in a closed glass vial in series with the nitrogen gas flow, a prompt exothermic signal on the left heat flow sensor was observed, accompanied by a positive quartz crystal microbalance signal

for the left quartz crystal microbalance to which the methanol vapor was introduced (the second event). After the aliquot of methanol had flushed through the sample chamber and was replaced by pure flowing nitrogen gas, the methanol adsorbed on the quartz crystal microbalance desorbed, and the heat flow sensor exhibited a corresponding slow
5 endothermic signal while the quartz crystal microbalance signal returned to its value before the introduction of methanol. The same event was repeated in the fourth event, with similar signals being observed. For some reason as yet not understood, injection of a corresponding amount of methanol vapor on the right, or reference, quartz crystal microbalance and heat flow sensor combination device in the third event did not produce
10 as large a signal. This could be due to differences in flow and a possible leak on the right hand side. In the fifth event, 10 microliters of hexane replaced the 10 microliters of methanol in a repeat of the second and fourth events and gave a slight exothermic signal in the left heat flow sensor, accompanied by a positive quartz crystal microbalance signal from the left quartz crystal microbalance.

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A further series of experiments showed definitively that the combined quartz crystal microbalance and heat flow sensor sample and reference devices respond in both channels to the adsorption and desorption of several organic vapors on the bare gold surface of each quartz crystal microbalance. The full time series from the quartz crystal
20 microbalance and from each of the two heat flow sensors are shown in Figures 13 and 14, respectively. This set of experiments took about four hours to perform. A slight difference between event times in the quartz crystal microbalance trace and the heat flow sensor trace is due to a small difference in time scale calibrations for the two channels, which could be corrected by computer software, but was not corrected for these
25 experiments. Figures 15 and 16 show the quartz crystal microbalance and heat flow sensor responses to 0.5 mL aliquots of toluene vapor injected in the gas flow to the left (signal A) and right (signal B) quartz crystal microbalance and heat flow sensor combination devices, respectively. Figures 17 and 18 show similar experiments with chloroform vapor. Figures 19 and 20 show the quartz crystal microbalance and heat flow
30 sensor responses with n-butanol vapor.

Still another aspect of the present invention pertains to a mass and heat flow measurement apparatus comprising (i) a gas sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to the first heat flow sensor, wherein the first heat flow sensor is thermally coupled to the first microresonator; and further wherein the first microresonator comprises a coated surface and is capable of measuring the changes in mass when a gas reacts with, is adsorbed, or is desorbed from the coated surface; and the first heat flow sensor is capable of measuring the flow of heat from the coated surface to the heat sink; (ii) a gas reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to the second microresonator, and a heat sink coupled thermally to the second heat flow sensor; and, (iii) a chamber housing the gas sample and gas reference sensors, wherein the gas reference sensor is isolated from the gas in contact with the first microresonator; and further wherein the second microresonator is capable of measuring a reference signal relating to mass at a surface of the second microresonator, and the second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of the second microresonator to the heat sink coupled thermally to the second heat flow sensor. In one embodiment, the chamber further comprises a gas input lead for introducing the gas into contact to the coated surface of the first microresonator and a gas output lead for removing the gas from contact to the coated surface of the first microresonator.

Yet another aspect of the present invention pertains to a mass and heat flow measurement system comprising (i) at least one mass and heat flow measurement gas sample sensor comprising a microresonator, a heat flow sensor coupled thermally to the microresonator, and a heat sink coupled thermally to the heat flow sensor, wherein the microresonator comprises a coated surface and generates data relating to the changes in mass on the coated surface of the microresonator arising from contacting the coated surface with a gas; and further wherein the heat flow sensor generates data relating to the changes in flow of heat from the coated surface to the heat sink from contacting the

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coated surface with the gas; (ii) at least one mass and heat flow measurement gas reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to the reference microresonator, and a heat sink coupled thermally to the reference heat flow sensor, wherein the microresonator of the gas reference sensor is not in contact with the gas in contact with the microresonator of the gas sample sensor; and further wherein the reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator, and the reference heat flow sensor generates data relating to the changes in flow of heat from the surface of the reference microresonator to the heat sink coupled thermally to the reference heat flow sensor; and, (iii) a measurement instrument capable of correlating the data from the gas sample and gas reference sensors so as to provide measurement of the changes in mass on the coated surface of the microresonator of the gas sample sensor and the flow of heat from the coated surface to the heat sink coupled thermally to the heat flow sensor of the gas sample sensor. In one embodiment, the system further comprises a gas input lead for introducing the gas into contact to the coated surface of the microresonator of the gas sample sensor and a gas output lead for removing the gas from contact to the coated surface of the microresonator of the gas sample sensor.

Another aspect of the present invention pertains to a heat flow measurement apparatus comprising (i) a liquid sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to the first heat flow sensor, wherein the first heat flow sensor is thermally coupled to the first microresonator; and further wherein the first microresonator is capable of measuring a signal relating to mass at a surface of the first microresonator, and the first heat flow sensor is capable of measuring the flow of heat from a liquid sample disposed on the first microresonator to the heat sink; (ii) a liquid reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to the second microresonator, and a heat sink coupled thermally to the second heat flow sensor; and, (iii) a chamber housing the liquid sample and liquid reference sensors, wherein the liquid reference sensor is isolated from the liquid sample in contact with the first microresonator; and further wherein the second microresonator is

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capable of measuring a reference signal relating to mass at a surface of the second microresonator, and the second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of the second microresonator to the heat sink coupled thermally to the second heat flow sensor. In one embodiment of the heat flow apparatus of this invention, the chamber further comprises a liquid input lead for introducing the liquid sample into contact to the first microresonator. In one embodiment, the first microresonator is capable of measuring the mass of the liquid sample in contact with the first microresonator.

10 Still another aspect of this invention pertains to a heat flow measurement system comprising (i) at least one heat flow measurement liquid sample sensor comprising a microresonator, a heat flow sensor coupled thermally to the microresonator, and a heat sink coupled thermally to the heat flow sensor, wherein the microresonator is capable of measuring a signal relating to mass at a surface of the microresonator; and further wherein
15 the heat flow sensor generates data relating to the changes in the flow of heat from a liquid sample to the heat sink from contacting the microresonator with the liquid sample; (ii) at least one heat flow measurement liquid reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to the reference microresonator, and a heat sink coupled thermally to the reference heat flow sensor,
20 wherein the microresonator of the reference sensor is not in contact with the liquid sample in contact with the microresonator of the liquid sample sensor; and further wherein the reference microresonator is capable of measuring a reference signal relating to mass at a surface of the reference microresonator, and the reference heat flow sensor generates data relating to the changes in flow of heat from the surface of the reference microresonator to
25 the heat sink coupled thermally to the reference heat flow sensor; and, (iii) a measurement instrument capable of correlating the data from the liquid sample and liquid reference sensors so as to provide measurement of the flow of heat from the liquid sample to the heat sink coupled thermally to the heat flow sensor of the liquid sample sensor. In one embodiment of the heat flow measurement system of the present invention, the system
30 further comprises a liquid input lead for introducing the liquid sample to the

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microresonator of the liquid sample sensor. In one embodiment, the microresonator of the liquid sample sensor generates data relating to the changes in mass on a surface of the microresonator of the liquid sample sensor, which data arises from contacting the microresonator of the liquid sample sensor with the liquid sample; wherein the reference
5 microresonator generates data relating to the changes in mass on a surface of the reference microresonator; and further wherein the measurement instrument is capable of correlating the data from the liquid sample and liquid reference sensors so as to further provide measurement of the mass of the liquid sample. In one embodiment, the mass of the liquid sample is known.

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Applications of the Mass and Heat Apparatus and System to Measure Enthalpies of Sublimation

In his review of trends in isothermal microcalorimetry in *Chemical Society*
15 *Reviews*, Volume 1997, pages 79-86 (1997), Wadsö states:

“There is a strong need for enthalpy of sublimation data for substances with very low vapor pressures, for example in connection with investigations of biothermodynamic model systems. However, very little development work and
20 few measurements have been reported during the last few decades in vaporization/sublimation calorimetry. More advanced microcalorimetric techniques are much needed in this field.”

Isothermal heat conduction calorimetry has been used to measure ΔH_{sub} for
25 compounds with vapor pressures as low as 10^{-6} torr, as, for example, described in *Chemical Scripta*, Vol. 1, pages 103-111 (1971) by Morawetz and in *Thermochimica Acta*, Vol. 115, pages 153-165 (1987) by Sabbah *et al.* Knudsen effusion methods, which use the Clausius-Clapeyron equation to derive ΔH_{sub} from the variation of vapor pressure with temperature, as, for example, described in *J. Chem. Thermo.*, Vol. 27, pages 1261-
30 1266 (1995) by Torres *et al.*, have been used on compounds with vapor pressures in the

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same range. Because many interesting organic and biological substances have room temperature vapors lower than these limits, their enthalpies of sublimation have not yet been measured. Yet for an accurate determination of the Gibbs free energy of formation, the heat of sublimation must be known. The energetics of formation of such substances in the gas phase is of great importance in determining the chemical reactivity of the substance, and in comparing with quantum chemical calculations of the same quantity.

The microresonator and heat flow sensor combination device can be used to measure sublimation enthalpies of quite non-volatile materials. The relationship between the sublimation rate of a solid, σ (moles $\text{m}^{-2} \text{s}^{-1}$), and its vapor pressure was first presented by Langmuir in *Physical Review*, Vol. 2, 329 (1913), as follows:

$$\sigma = P_{eq} / \sqrt{2\pi MRT}$$

Here, P_{eq} is the equilibrium vapor pressure of the solid, M is its molar mass, R is the gas constant, and T is the absolute temperature. For the hypothetical solid described above, with a sublimation enthalpy of 50 kJ/mol and a molar mass of 200g/mole, a surface area of 1 cm^2 will lose mass at the rate of 1.0 ng/sec if the vapor pressure of the solid is 2.0×10^{-8} torr.

From the design perspective, it is helpful to use as large a diameter, D , for the microresonator as possible, since this permits a larger sample area ($\pi d^2/4$, Figure 1) and thus a larger thermal signal. Of importance in evacuating the microresonator and heat flow sensor combination apparatus and system is the nature of the piezoelectric substrate-to-metal contact, such as quartz-to-metal contact, (for example, o-ring, direct contact without bonding, or a high-vacuum seal), since the underside of the quartz crystal must not be subject to adsorbing vapors from the sample.

Applications of the Mass and Heat Flow Apparatus and System to Energy-Sensitive Chemical Sensors

There is a large and actively growing literature on specific and sensitive chemical sensors based on surface-coated microresonator, such as quartz crystal oscillator, technology. For example, *Sensors and Actuators B*, Vol. 18-19, pages 429-433 (1994) by Hartmann *et al.*, describes use of a quartz crystal microbalance coated with polymers, with lipophilic compounds, with calix-n-arenes, with complex formers, and with a monomolecular layer to explore the sensitivity and selectivity of quartz crystal microbalance-based gas sensors. Also, for example, *Sensors and Actuators B*, Vol. 34, pages 356-360 (1996) by Zhou *et al.*, describes coating both a quartz crystal microbalance and a separate calorimetric transducer with a cycloaliphatic poly(ether urethane) to detect organic solvent vapors. However, there has been no report of a combined microresonator and heat flow sensor combination used as a gas sensor. Since the combined microresonator and heat flow sensor combination apparatus and system give a real-time measurement of the molar heat of adsorption, it has a powerful additional measurement dimension which should provide further selectivity for gas sensors. There are also many fundamental problems of interest to study with the microresonator and heat flow sensor combination apparatus and system, such as, for example, the continuous variation in molar enthalpy with increasing surface coverage from adsorption of a monolayer to condensation of the bulk solid.

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Applications of the Mass and Heat Flow Apparatus and System to Measuring the Binding Enthalpy of Water in Biological Materials

If a protein in solution is coated on the microresonator, such as a quartz crystal microbalance, at high water vapor pressure or relative humidity, the decrease in mass and the heat required for evaporation of water may be studied by varying the partial pressure of water in the gas above the surface. At first, one should expect the thermal signal to be almost the same as the enthalpy of vaporization of water itself, but as more and more water is removed, the binding energy per water molecule should change to that more

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representative of protein molecule-water interaction energies. Such studies should help to elucidate the binding energetics of water in any biological material.

Other Applications of the Mass and Heat Flow Apparatus and System

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The microresonator and heat flow sensor combination apparatus and system measure simultaneously and continuously, with high sensitivity (nanogram in mass, sub-microwatt in heat flow), the change in mass and heat flow at a small gas-solid interface of, for example, about 1 cm², due to chemical processes such as evaporation or condensation, adsorption or desorption, or gas-surface reactions. Other potential applications of the microresonator and heat flow sensor combination apparatus and system include, but are not limited to, the study of:

(a) the hydration and dehydration of films of proteins and other biomolecules deposited on solid substrates. These films are used, for example, in biosensors, diagnostic immunoassays, the separation of proteins by chromatography, and as models for biological and biocompatible membranes and surfaces;

(b) the energetics of intermolecular interactions at the surface of polymer films and other organic surfaces important in adhesion, lubrication, wetting, and corrosion; and,

(c) the energetics of the drying and curing of both water-based and organic solvent-based paints and finishes.

Methods for Measuring Mass and Heat Flow of Samples

Another aspect of the present invention pertains to a method for measuring the mass of a sample and the flow of heat from the sample to a heat sink, which method comprises the steps of: (i) contacting the sample with a mass and heat flow measurement system, as described herein; (ii) obtaining data from both the sample and reference sensors of the mass and heat flow measurement system of the present invention; and, (iii) determining the mass of the sample and the flow of heat from the sample to the heat sink

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coupled thermally to the heat flow sensor of the sample sensor. In one embodiment, the sample is a solid sample, and, preferably, the method of this invention measures the enthalpy of sublimation of the solid sample.

5 As described herein, in the apparatus, systems, and methods of the present invention, the change in mass of the sample is measured by a change in the frequency of the piezoelectric substrate of the microresonator, and the change in the flow of heat from the sample to the heat sink is typically measured by a change in the voltage output of the heat flow sensor. Suitable electrical circuitry and data collection and correlation
10 equipment and methods for these measurements include, but are not limited to, those described for microresonators in the afore-mentioned references by Grate *et al.*, Alder *et al.*, McCallum, and Lu *et al.*, and for heat flow sensors in the afore-mentioned review article by Wadso^{''} and references therein.

15 Another aspect of the present invention pertains to a method for measuring the change in mass and flow of heat from a coated surface to a heat sink when a gas reacts with, is adsorbed, or is desorbed from the coated surface, which method comprises the steps of: (i) contacting the gas with a mass and heat flow gas measurement system, as described herein; (ii) obtaining data from both the gas sample and gas reference sensors of
20 the mass and heat flow gas measurement system of this invention; and, (iii) determining the changes in mass and the flow of heat from the coated surface of the microresonator of the gas sample sensor to the heat sink coupled thermally to the heat flow sensor of the gas sample sensor, which changes arise when the gas reacts with, is adsorbed, or is desorbed from the coated surface. In one embodiment of the method, the mass and heat flow gas
25 measurement system further comprises a gas input lead for introducing the gas to the microresonator of the gas sample sensor and a gas output lead for removing the gas from contact to the microresonator of the gas sample sensor. In one embodiment, the method measures the molar heat of adsorption of the gas, and, preferably, the molar heat of adsorption is measured in real time. In one embodiment, the reference microresonator
30 comprises a coated surface. In one embodiment, the coated surface of the reference

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microresonator comprises the same coating as the coated surface of the microresonator of the gas sample sensor. In one embodiment, the method measures the molar heat of reaction of the gas with the coated surface, and, preferably, the molar heat of reaction is measured in real time. In one embodiment, the method measures the molar heat of desorption of the gas, and, preferably, the molar heat of desorption is measured in real time. In one embodiment, the microresonator of the gas sample sensor and the reference microresonator are selected from the group of microresonators consisting of: bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the microresonator of the gas sample sensor and the reference microresonator are quartz crystal microbalances.

Another aspect of the present invention pertains to a method for measuring the change in the flow of heat from a liquid sample to a heat sink, which method comprises the steps of: (i) contacting the liquid sample with a heat flow measurement system, as described herein; (ii) obtaining data from both the liquid sample and liquid reference sensors of the heat flow measurement system of this invention; and, (iii) determining the flow of heat from the liquid sample to the heat sink coupled thermally to the heat flow sensor of the liquid sample sensor. In one embodiment, the heat flow measurement system further comprises a liquid input lead for introducing the liquid sample to the microresonator of the liquid sample sensor. In one embodiment, the microresonator of the liquid sample sensor generates data relating to the changes in mass on a surface of the microresonator of the liquid sample sensor, which data arises from contacting the microresonator of the liquid sample sensor with the liquid sample; wherein the reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator; and further wherein the measurement instrument is capable of correlating the data from the liquid sample and liquid reference sensors so as to further provide measurement of the mass of the liquid sample. In one embodiment, the mass of the liquid sample is known. In one embodiment, the method measures the molar heat of evaporation of the liquid sample. In one embodiment, the microresonator of the liquid sample sensor

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comprises a coated surface, and, preferably, the reference microresonator also comprises a coated surface, and, most preferably, the coated surface of the reference microresonator comprises the same coating as the coated surface of the microresonator of the liquid sample sensor. In one embodiment, the microresonator of the liquid sample sensor and
5 the reference microresonator are selected from the group of microresonators consisting of: bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors. In a preferred embodiment, the microresonator of the liquid sample sensor and the reference microresonator are quartz crystal microbalances.

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While the invention has been described in detail and with reference to specific embodiments thereof, it will be apparent to one skilled in the art that various changes and modifications can be made without departing from the spirit and scope thereof.

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CLAIMS

1. A mass and heat flow measurement apparatus comprising:
 - 5 (a) a sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to said first heat flow sensor, wherein said first heat flow sensor is thermally coupled to said first microresonator; and further wherein said first microresonator is capable of measuring the mass of a sample in contact with said first microresonator, and said first heat flow sensor is capable of
10 measuring the flow of heat from the sample to the heat sink;
 - (b) a reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to said second microresonator, and a heat flow sink coupled thermally to said second heat flow sensor; and,
 - (c) a chamber housing said sample and reference sensors, wherein said reference
15 sensor is isolated from the sample; and further wherein said second microresonator is capable of measuring a reference signal relating to mass at a surface of said second microresonator, and said second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of said second microresonator to the heat sink coupled thermally to said second heat flow
20 sensor.
2. The apparatus of claim 1, wherein said first microresonator comprises a piezoelectric substrate having a perimeter, a first face for directly contacting a sample, and a second opposite face isolated from contacting the sample; and further wherein said second
25 microresonator comprises a piezoelectric substrate having a perimeter, a first face, and a second opposite face, said piezoelectric substrates of said first and second microresonators having a resonant frequency and capable of providing a measurement signal based on said resonant frequency.

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3. The apparatus of claim 1, wherein said first and second microresonators are selected from the group of microresonators consisting of:

bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors.

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4. The apparatus of claim 3, wherein said first microresonator comprises a surface coating with an affinity for at least one component of the sample.

5. The apparatus of claim 4, wherein said second microresonator comprises a surface coating with an affinity for at least one component of the sample.

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6. The apparatus of claim 1, wherein said first and second microresonators are quartz crystal microbalances.

7. The apparatus of claim 1, wherein said first and second heat flow sensors comprise a thermopile.

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8. A mass and heat flow measurement system comprising:

- (a) at least one mass and heat flow measurement sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator generates data relating to the changes in mass on a surface of said microresonator arising from contacting said microresonator with a sample; and further wherein said heat flow sensor generates data relating to the changes in flow of heat from the sample to the heat sink from contacting said microresonator with the sample;
- (b) at least one mass and heat flow measurement reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat flow sensor, wherein the microresonator of said reference sensor is not in contact with the sample; and further wherein said reference microresonator generates data

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relating to the changes in mass on a surface of the reference microresonator, and said reference heat flow sensor generates data relating to the changes in flow of heat from the surface of said reference microresonator to the heat sink coupled thermally to said reference heat flow sensor; and,

- 5 (c) a measurement instrument capable of correlating the data from the sample and reference sensors so as to provide measurement of the mass of the sample and the flow of heat from the sample to the heat sink coupled thermally to the heat flow sensor of said sample sensor.

- 10 9. The system of claim 8, wherein the microresonator of said sample sensor comprises a piezoelectric substrate having a perimeter, a first face for directly contacting a sample, and a second opposite face isolated from contacting the sample; and further wherein said reference microresonator comprises a piezoelectric substrate having a perimeter, a first face, and a second opposite face, said piezoelectric substrates of said microresonator of
15 the sample sensor and said reference microresonator having a resonant frequency and capable of providing a measurement signal based on said resonant frequency.

10. The system of claim 8, wherein said microresonator of the sample sensor and said reference microresonator are selected from the group of microresonators consisting of:
20 bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors.

11. The system of claim 10, wherein said microresonator of the sample sensor comprises a surface coating with an affinity for at least one component of the sample.

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12. The system of claim 11, wherein said reference microresonator comprises a surface coating with an affinity for at least one component of the sample.

13. The system of claim 8, wherein said microresonator of the sample sensor and said
30 reference microresonator are quartz crystal microbalances.

14. The system of claim 8, wherein said heat flow sensor of the sample sensor and said reference heat flow sensor comprise a thermopile.

5 15. A method for measuring the mass of a sample and the flow of heat from the sample to a heat sink, which method comprises the steps of:

(a) contacting the sample with a mass and heat flow measurement system which comprises:

10 (i) at least one mass and heat flow measurement sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator generates data relating to the changes in mass on a surface of said microresonator arising from contacting said microresonator with the sample, and further wherein said heat flow sensor generates data relating to the changes in flow of heat from
15 the sample to the heat sink from contacting said microresonator with the sample;
(ii) at least one mass and heat flow measurement reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat flow sensor, wherein the microresonator of said reference sensor is not in contact
20 with the sample; and further wherein said reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator, and said reference heat flow sensor generates data relating to the changes in the flow of heat from the surface of said reference microresonator to the heat sink coupled thermally to the reference heat flow sensor; and,
25 (iii) a measurement instrument capable of correlating the data from the sample and reference sensors so as to provide measurement of the mass of the sample and the flow of heat from the sample to the heat sink coupled thermally to the heat flow sensor of said sample sensor;

(b) obtaining data from both the sample and reference sensors; and,

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(c) determining the mass of the sample and the flow of heat from the sample to the heat sink coupled thermally to the heat flow sensor of said sample sensor.

16. The method of claim 15, wherein the microresonator of said sample sensor comprises
5 a piezoelectric substrate having a perimeter, a first face for directly contacting a sample, and a second opposite face isolated from contacting the sample; and further wherein said reference microresonator comprises a piezoelectric substrate having a perimeter, a first face, and a second opposite face, said piezoelectric substrates of said microresonator of the sample sensor and said reference microresonator having a resonant frequency and
10 capable of providing a measurement signal based on said resonant frequency.

17. The method of claim 15, wherein said microresonator of the sample sensor and said reference microresonator are selected from the group of microresonators consisting of:
bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave
15 sensors, flexural plate wave sensors, and acoustic plate mode sensors.

18. The method of claim 17, wherein said microresonator of the sample sensor comprises a surface coating with an affinity for at least one component of the sample.

20 19. The method of claim 18, wherein said reference microresonator comprises a surface coating with an affinity for at least one component of the sample.

20. The method of claim 15, wherein said microresonator of the sample sensor and said reference microresonator are quartz crystal microbalances.

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21. The method of claim 15, wherein said heat flow sensor of the sample sensor and said reference heat flow sensor comprise a thermopile.

22. A mass and heat flow measurement apparatus comprising:

- (a) a gas sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to said first heat flow sensor, wherein said first heat flow sensor is thermally coupled to said first microresonator; and further wherein said first microresonator comprises a coated surface and is capable of measuring the changes in mass when a gas reacts with, is absorbed, or is desorbed from the coated surface, and said first heat flow sensor is capable of measuring the flow of heat from the coated surface to the heat sink;
- (b) a gas reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to said second microresonator, and a heat flow sink coupled thermally to said second heat flow sensor; and,
- (c) a chamber housing said gas sample and gas reference sensors, wherein said gas reference sensor is isolated from the gas in contact with said first microresonator; and further wherein said second microresonator is capable of measuring a reference signal relating to mass at a surface of said second microresonator, and said second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of said second microresonator to the heat sink coupled thermally to said second heat flow sensor.

23. The apparatus of claim 22, wherein said chamber further comprises a gas input lead for introducing the gas into contact to the coated surface of said first microresonator and a gas output lead for removing the gas from contact to the coated surface of said first microresonator.

24. A mass and heat flow measurement system comprising:

- (a) at least one mass and heat flow measurement gas sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator comprises a coated surface and generates data relating to the changes in mass on the coated surface of said microresonator arising from contacting the coated surface with a gas, and further wherein said heat flow sensor generates data

relating to the changes in flow of heat from the coated surface to the heat sink from contacting the coated surface with the gas;

- 5 (b) at least one mass and heat flow measurement gas reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat flow sensor, wherein the microresonator of said gas reference sensor is not in contact with the gas in contact with the microresonator of said gas sample sensor; and further wherein said reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator, and said reference heat flow sensor generates data relating to the changes in flow of heat from the surface of said reference microresonator to the heat sink coupled thermally to said reference heat flow sensor; and,
- 10 (c) a measurement instrument capable of correlating the data from the gas sample and gas reference sensors so as to provide measurement of the changes in mass on the coated surface of the microresonator of said gas sample sensor and the flow of heat from the coated surface to the heat sink coupled thermally to the heat flow sensor of said gas sample sensor.
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25. The system of claim 24, wherein said system further comprises a gas input lead for introducing the gas into contact to the coated surface of the microresonator of said gas sample sensor and a gas output lead for removing the gas from contact to the coated surface of the microresonator of said gas sample sensor.

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26. A method for measuring the change in mass and flow of heat from a coated surface to a heat sink when a gas reacts with, is absorbed, or is desorbed from the coated surface, which method comprises the steps of:

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- (a) contacting the gas with a mass and heat flow measurement system which comprises:
- (i) at least one mass and heat flow measurement gas sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator
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- comprises a coated surface and generates data relating to the changes in mass on the coated surface of said microresonator arising from contacting the coated surface with the gas; and further wherein said heat flow sensor generates data relating to the changes in flow of heat from the coated surface to the heat sink from contacting the coated surface with the gas;
- 5 (ii) at least one mass and heat flow measurement gas reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat flow sensor, wherein the microresonator of said gas reference sensor is not in
- 10 contact with the gas in contact with the microresonator of said gas sample sensor; and further wherein said reference microresonator generates data relating to changes in mass on a surface of said reference microresonator, and said reference heat flow sensor generates data relating to the changes in the flow of heat from the surface of said reference microresonator to the heat sink coupled
- 15 thermally to said reference heat flow sensor; and,
- (iii) a measurement instrument capable of correlating the data from the gas sample and gas reference sensors so as to provide measurement of the changes in mass on the coated surface of the microresonator of said gas sample sensor and the flow of heat from the coated surface to the heat sink coupled thermally to the heat flow
- 20 sensor of said gas sample sensor;
- (b) obtaining data from both the gas sample and gas reference sensors; and,
- (c) determining the changes in mass and the flow of heat from the coated surface of the microresonator of said gas sample sensor to the heat sink coupled thermally to the heat flow sensor of said gas sample sensor, which changes arise when the gas reacts with, is
- 25 absorbed, or is desorbed from the coated surface.

27. The method of claim 26, wherein said mass and heat flow measurement system further comprises a gas input lead for introducing the gas to the microresonator of said gas sample sensor and a gas output lead for removing the gas from contact to the
- 30 microresonator of said gas sample sensor.

28. The method of claim 26, wherein said method measures the molar heat of absorption of said gas.

5 29. The method of claim 28, wherein said molar heat of absorption is measured in real time.

30. The method of claim 26, wherein said reference microresonator comprises a coated surface.

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31. The method of claim 30, wherein the coated surface of said reference microresonator comprises the same coating as the coated surface of the microresonator of said gas sample sensor.

15 32. The method of claim 26, wherein said method measures the molar heat of reaction of said gas with said coated surface.

33. The method of claim 32, wherein said molar heat of reaction is measured in real time.

20 34. The method of claim 26, wherein said method measures the molar heat of desorption of said gas.

35. The method of claim 34, wherein said molar heat of desorption is measured in real time.

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36. The method of claim 26, wherein said microresonator of the gas sample sensor and said reference microresonator are selected from the group of microresonators consisting of:

30 bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors.

37. The method of claim 26, wherein said microresonator of the gas sample sensor and said reference microresonator are quartz crystal microbalances.

5 38. A heat flow measurement apparatus comprising:

- 10 (a) a liquid sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to said first heat flow sensor, wherein said first heat flow sensor is thermally coupled to said first microresonator; and further wherein said first microresonator is capable of measuring a signal relating to mass at a surface of said first microresonator, and said first heat flow sensor is capable of measuring the flow of heat from a liquid sample disposed on said first microresonator to the heat sink;
- 15 (b) a liquid reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to said second microresonator, and a heat flow sink coupled thermally to said second heat flow sensor; and,
- 20 (c) a chamber housing said liquid sample and liquid reference sensors and wherein said liquid reference sensor is isolated from the liquid sample in contact with said first microresonator; and further wherein said second microresonator is capable of measuring a reference signal relating to mass at a surface of said second microresonator and said second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of said second microresonator to the heat sink coupled thermally to said second heat flow sensor.

25 39. The apparatus of claim 38, wherein said chamber further comprises a liquid input lead for introducing the liquid sample into contact to said first microresonator.

40. The apparatus of claim 38, wherein said first microresonator is capable of measuring the mass of the liquid sample in contact with said first microresonator.

30 41. A heat flow measurement system comprising:

- (a) at least one heat flow measurement liquid sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator is capable of measuring a signal relating to mass at a surface of said microresonator; and further wherein said heat flow sensor generates data relating to the changes in flow of heat from a liquid sample to the heat sink from contacting said microresonator with the liquid sample;
- (b) at least one heat flow measurement liquid reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat flow sensor, wherein the microresonator of said reference sensor is not in contact with the liquid sample in contact with the microresonator of said liquid sample sensor; and further wherein said reference microresonator is capable of measuring a reference signal relating to mass at a surface of said reference microresonator, and said reference heat flow sensor generates data relating to the changes in flow of heat from the surface of said reference microresonator to the heat sink coupled thermally to said reference heat flow sensor; and,
- (c) a measurement instrument capable of correlating the data from the liquid sample and liquid reference sensors so as to provide measurement of the flow of heat from the liquid sample to the heat sink coupled thermally to the heat flow sensor of said liquid sample sensor.

42. The system of claim 41, wherein said system further comprises a liquid input lead for introducing the liquid sample to the microresonator of said liquid sample sensor.

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43. The system of claim 41, wherein the microresonator of said liquid sample sensor generates data relating to the changes in mass on a surface of the microresonator of said liquid sample sensor, which data arises from contacting the microresonator of said liquid sample sensor with the liquid sample; wherein said reference microresonator generates data relating to the changes in mass on a surface of said reference microresonator; and

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further wherein said measurement instrument is capable of correlating the data from the liquid sample and liquid reference sensors so as to further provide measurement of the mass of the liquid sample.

5 44. The system of claim 41, wherein the mass of said liquid sample is known.

45. A method for measuring the change in the flow of heat from a liquid sample to a heat sink, which method comprises the steps of:

(a) contacting the liquid sample with a heat flow measurement system which comprises:

- 10 (i) at least one heat flow measurement liquid sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator is capable of measuring a signal relating to mass at a surface of said microresonator; and further wherein said heat flow sensor generates data relating
- 15 to the changes in flow of heat from the liquid sample to the heat sink from contacting said coated surface with the liquid sample;
- (ii) at least one heat flow measurement liquid reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat
- 20 flow sensor, wherein said reference microresonator is not in contact with the liquid sample in contact with the microresonator of said liquid sample sensor; and further wherein said reference microresonator is capable of measuring a reference signal relating to mass at a surface of said reference microresonator, and said reference heat flow sensor generates data relating to the changes in the flow of heat from the
- 25 surface of said reference microresonator to the heat sink coupled thermally to said reference heat flow sensor; and,
- (iii) a measurement instrument capable of correlating the data from the liquid sample and liquid reference sensors so as to provide measurement of the flow of heat from the liquid sample to the heat sink coupled thermally to the heat flow
- 30 sensor of said liquid sample sensor;

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(b) obtaining data from both the liquid sample and liquid reference sensors; and,
(c) determining the flow of heat from the liquid sample to the heat sink coupled thermally to the heat flow sensor of said liquid sample sensor.

5 46. The method of claim 45, wherein said heat flow measurement system further comprises a liquid input lead for introducing the liquid sample to the microresonator of said liquid sample sensor.

10 47. The method of claim 45, wherein the microresonator of said liquid sample sensor generates data relating to the changes in mass on a surface of the microresonator of said liquid sample sensor, which data arises from contacting the microresonator of said liquid sample sensor with the liquid sample; wherein said reference microresonator generates data relating to the changes in mass on a surface of said reference microresonator; and
15 further wherein said measurement instrument is capable of correlating the data from the liquid sample and liquid reference sensors so as to further provide measurement of the mass of the liquid sample.

48. The method of claim 45, wherein the mass of said liquid sample is known.

20 49. The method of claim 47, wherein method measures the molar heat of evaporation of said liquid sample.

50. The method of claim 45, wherein said microresonator of the liquid sample sensor comprises a coated surface.

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51. The method of claim 50, wherein said reference microresonator comprises a coated surface.

52. The method of claim 51, wherein the coated surface of said reference microresonator comprises the same coating as the coated surface of said microresonator of the liquid sample sensor.

5 53. The method of claim 45, wherein said microresonator of the liquid sample sensor and said reference microresonator are selected from the group of microresonators consisting of:

bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors.

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54. The method of claim 45, wherein said microresonator of the liquid sample sensor and said reference microresonator are quartz crystal microbalances.

55. A mass and heat flow measurement apparatus comprising:

- 15 (a) a solid sample sensor comprising a first microresonator, a first heat flow sensor, and a heat sink coupled thermally to said first heat flow sensor, wherein said first heat flow sensor is thermally coupled to said first microresonator; and further wherein said first microresonator is capable of measuring the mass of a solid sample in contact with said first microresonator, and said first heat flow sensor is
- 20 capable of measuring the flow of heat from the solid sample to the heat sink;
- (b) a solid reference sensor comprising a second microresonator, a second heat flow sensor coupled thermally to said second microresonator, and a heat flow sink coupled thermally to said second heat flow sensor; and,
- (c) a chamber housing said solid sample and solid reference sensors, wherein said
- 25 solid reference sensor is isolated from the solid sample in contact with said first microresonator; and further wherein said second microresonator is capable of measuring a reference signal relating to mass at a surface of said second microresonator and said second heat flow sensor is capable of measuring a reference signal relating to the flow of heat from the surface of said second
- 30 microresonator to the heat sink coupled thermally to said second heat flow sensor.

56. A mass and heat flow measurement system comprising:

- 5 (a) at least one mass and heat flow measurement solid sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator generates data relating to the changes in mass on a surface of said microresonator arising from contacting said microresonator with a solid sample; and further wherein said heat flow sensor generates data relating to the changes in flow of heat from the solid sample to the heat sink from contacting said microresonator with
- 10 the solid sample;
- (b) at least one mass and heat flow measurement solid reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat flow sensor, wherein said reference microresonator is not in contact with the solid
- 15 sample in contact with the microresonator of said solid sample sensor; and further wherein said reference microresonator generates data relating to the changes in mass on a surface of the reference microresonator, and said reference heat flow sensor generates data relating to the changes in flow of heat from the surface of said reference microresonator to the heat sink coupled thermally to said reference
- 20 heat flow sensor; and,
- (c) a measurement instrument capable of correlating the data from the solid sample and solid reference sensors so as to provide measurement of the mass of the solid sample and the flow of heat from the solid sample to the heat sink coupled thermally to the heat flow sensor of said solid sample sensor.

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57. A method for measuring the change in mass of a solid sample and the flow of heat from the solid sample to a heat sink, which method comprises the steps of:

- (a) contacting the solid sample with a mass and heat flow measurement system which comprises:

- 5 (i) at least one mass and heat flow measurement solid sample sensor comprising a microresonator, a heat flow sensor coupled thermally to said microresonator, and a heat sink coupled thermally to said heat flow sensor, wherein said microresonator generates data relating to the changes in mass on a surface of said microresonator arising from contacting said microresonator with the solid sample; and further wherein said heat flow sensor generates data relating to the changes in flow of heat from the solid sample to the heat sink from contacting said microresonator with the solid sample;
- 10 (ii) at least one mass and heat flow measurement solid reference sensor comprising a reference microresonator, a reference heat flow sensor coupled thermally to said reference microresonator, and a heat sink coupled thermally to said reference heat flow sensor, wherein said reference microresonator is not in contact with the solid sample in contact with the microresonator of said solid sample sensor; and further wherein said reference microresonator generates data relating to changes in mass
- 15 on a surface of said reference microresonator, and said reference heat flow sensor generates data relating to the changes in the flow of heat from the surface of said reference microresonator to the heat sink coupled thermally to said reference heat flow sensor; and,
- 20 (iii) a measurement instrument capable of correlating the data from the solid sample and solid reference sensors so as to provide measurement of the mass of the solid sample and the flow of heat from the solid sample to the heat sink coupled thermally to the heat flow sensor of said solid sample sensor;
- (b) obtaining data from both the solid sample and solid reference sensors; and,
- (c) determining the mass of the solid sample and the flow of heat from the solid sample to
- 25 the heat sink coupled thermally to the heat flow sensor of said solid sample sensor.

58. The method of claim 57, wherein said microresonator of the solid sample sensor and said reference microresonator are selected from the group of microresonators consisting of:

bulk acoustic wave sensors, quartz crystal microbalances, surface acoustic wave sensors, flexural plate wave sensors, and acoustic plate mode sensors.

59. The method of claim 57, wherein said microresonator of the solid sample sensor and
5 said reference microresonator are quartz crystal microbalances.

60. The method of claim 57, wherein said microresonator of the solid sample sensor
comprises a coated surface.

10 61. The method of claim 60, wherein said reference microresonator comprises a coated
surface.

62. The method of claim 61, wherein the coated surface of said reference microresonator
comprises the same coating as the coated surface of said microresonator of the solid
15 sample sensor.

63. The method of claim 57, wherein said method measures the molar enthalpy of
sublimation of said solid sample.

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**Adiabatic
vs.
Heat Conduction
Calorimetry**

Adiabatic: temperature vs. time is measured in an adiabatic vessel of known heat capacity

$$Q = C\Delta T$$

Heat Conduction: thermal power vs. time is measured in a vessel in which the heat generated by the chemical process flows through a heat flow sensor

$$Q = \int (dQ/dt) dt$$

Fig. 1

Basic Equations for Heat Conduction Calorimetry ("Calvet calorimetry")

$$P = \frac{1}{S} \left[U + \tau \left(\frac{dU}{dt} \right) \right]$$

where

P = thermal power (watts)

S = thermopile sensitivity
(volts/watt)

U = thermopile voltage (volts)

τ = time constant of the
calorimeter (seconds)

At steady state,

$$U = S P$$

Time constant:

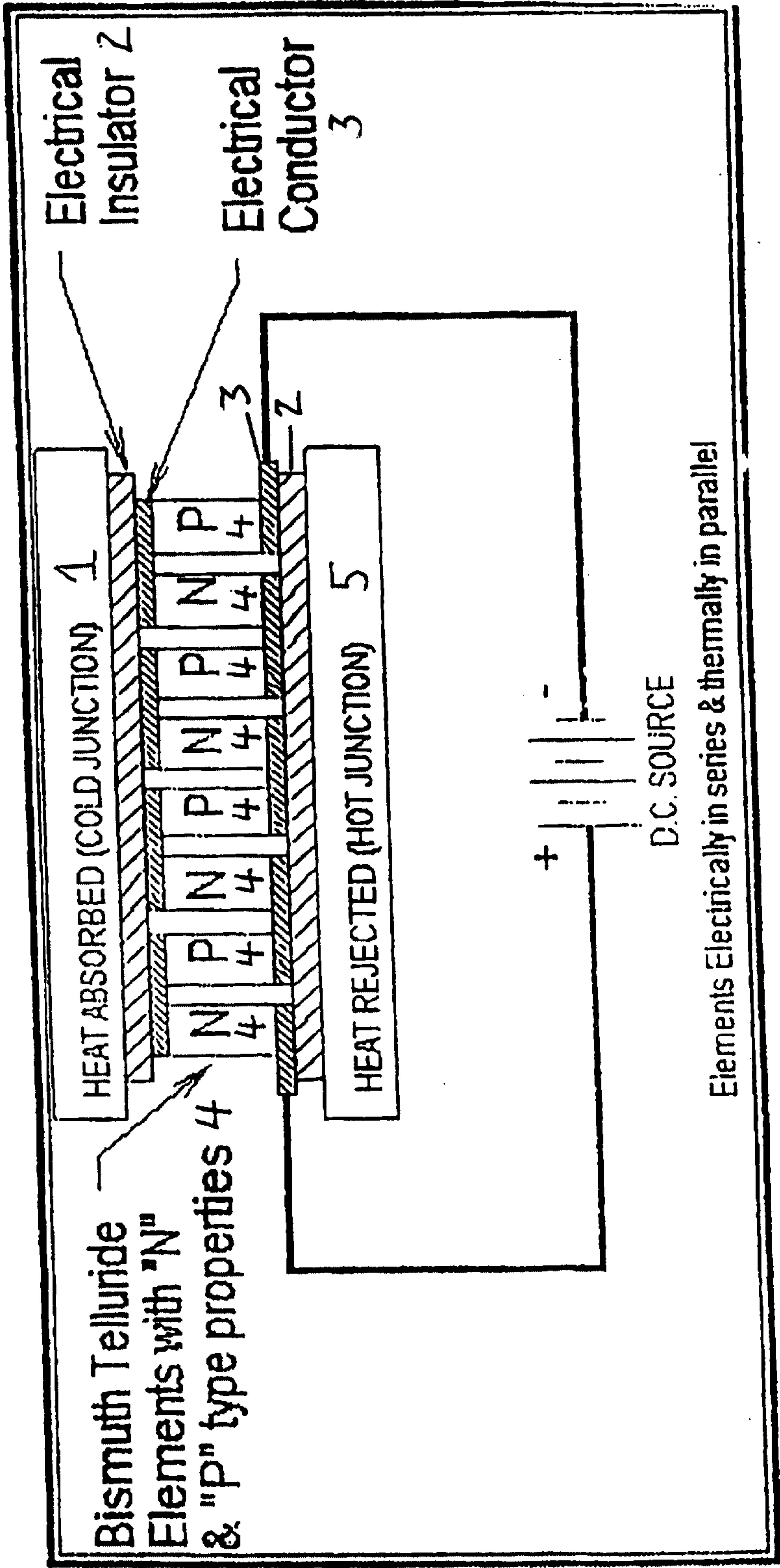
$$\tau = C/G,$$

where

C = reaction vessel heat capacity

G = thermopile thermal
conductance

Fig. 2



Typical TE Module Assembly

In practical use, couples are combined in a module where they are connected electrically in series, and thermally in parallel. Normally a module is the smallest component commercially available.

Modules are available in a great variety of sizes, shapes, operating currents, operating voltages and ranges of heat pumping capacity. The present trend, however, is toward a larger number of couples operating at lower currents. The user can select the quantity, size or capacity of the module to

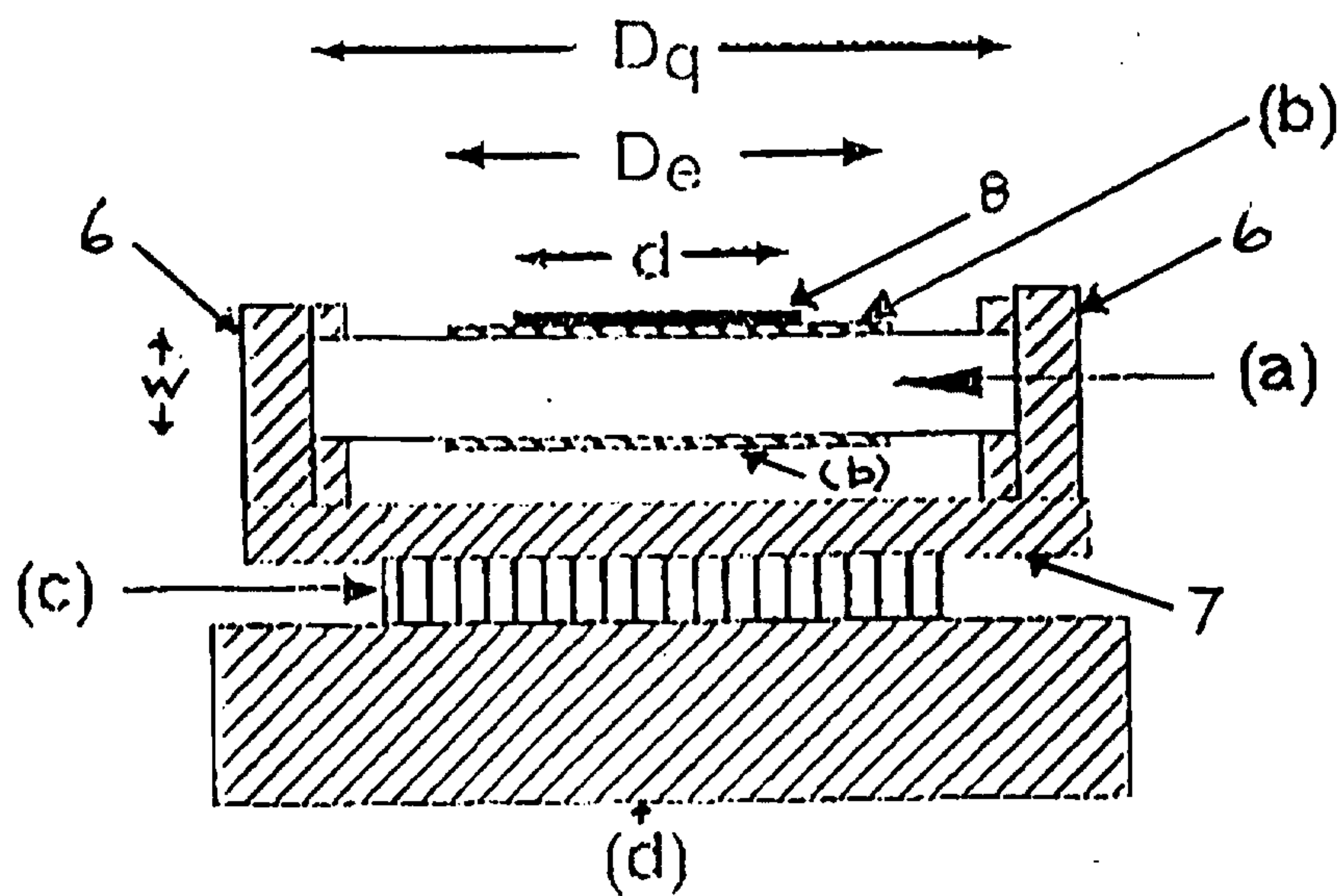


Fig. 4

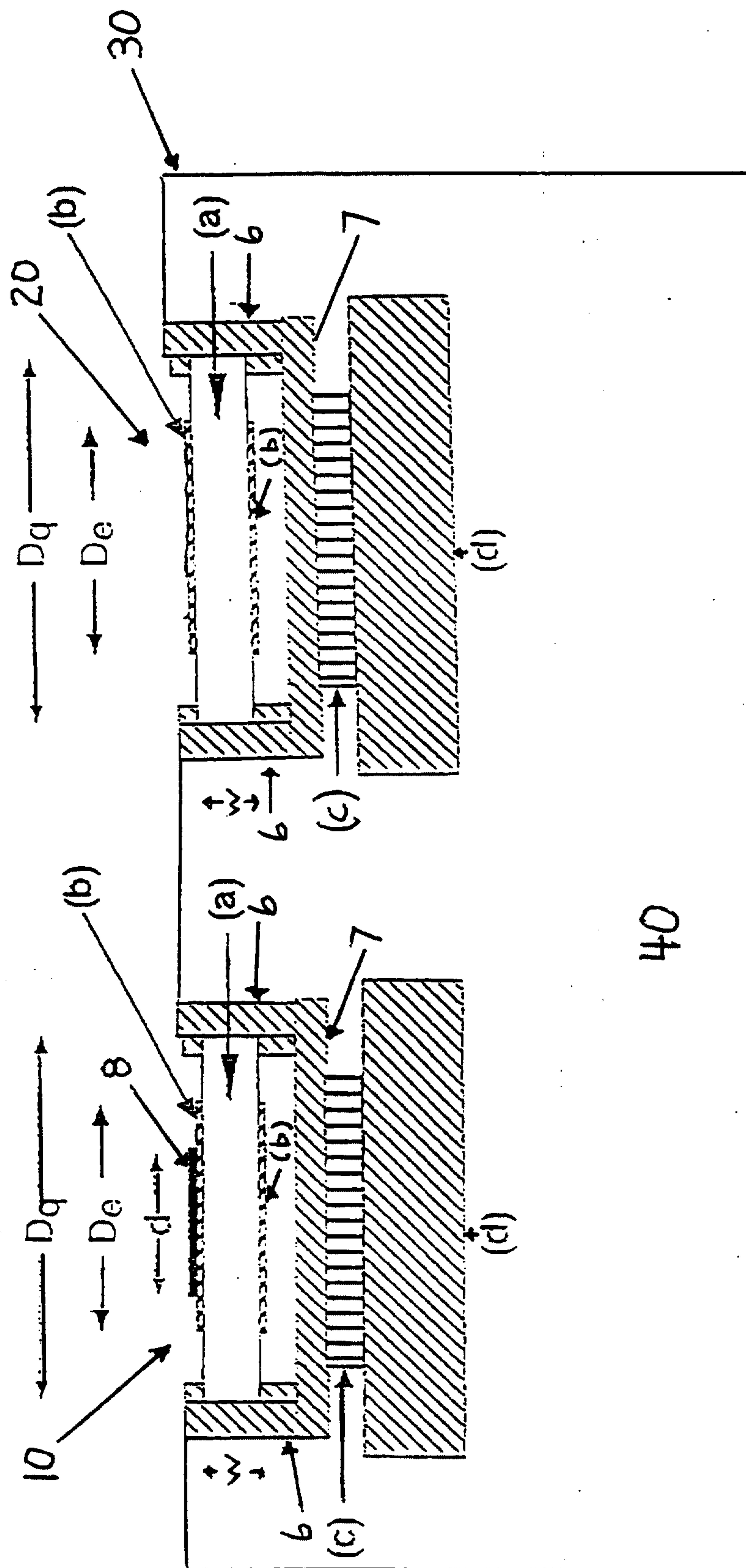


Fig. 5.

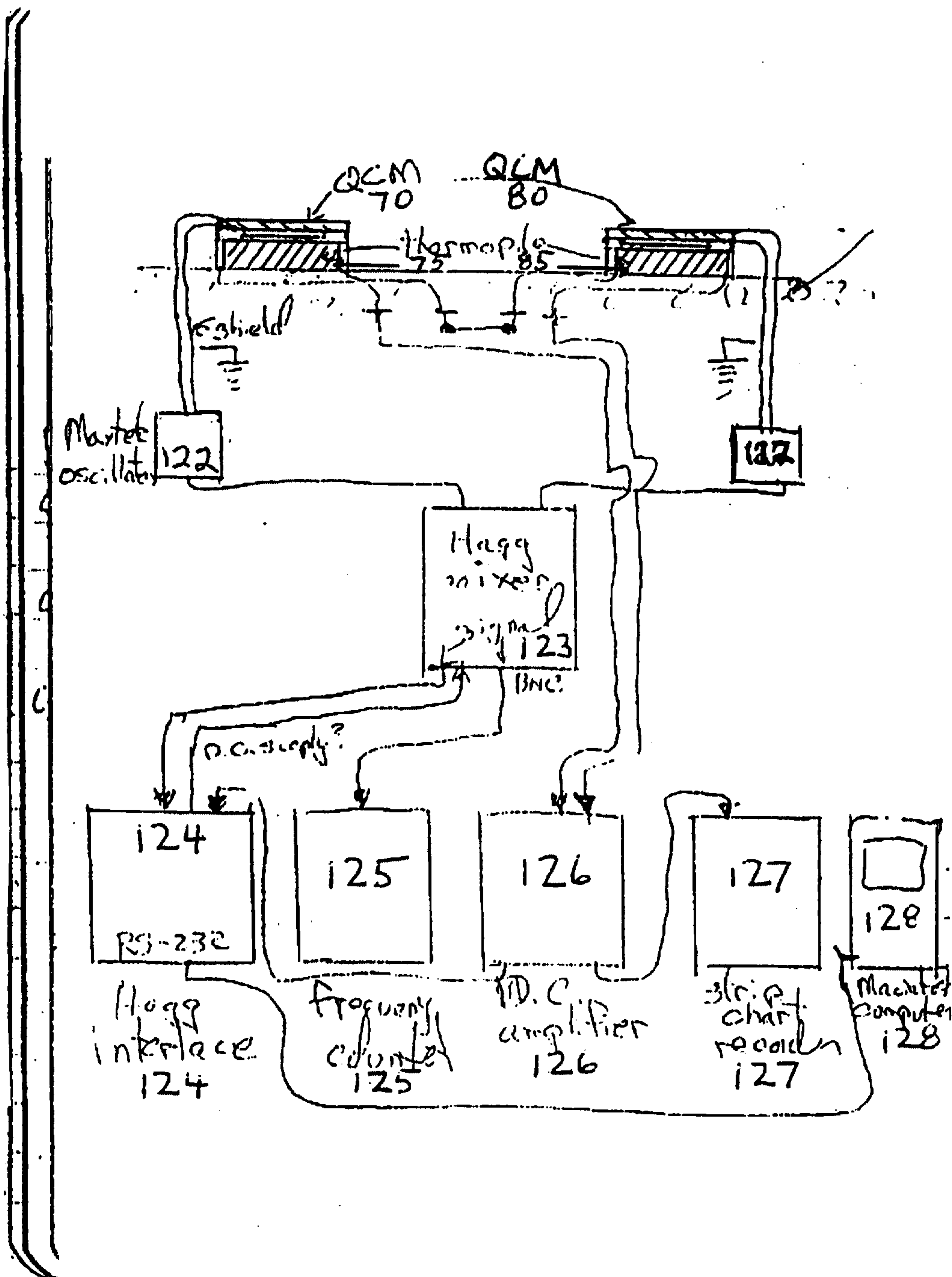


Fig. 6a

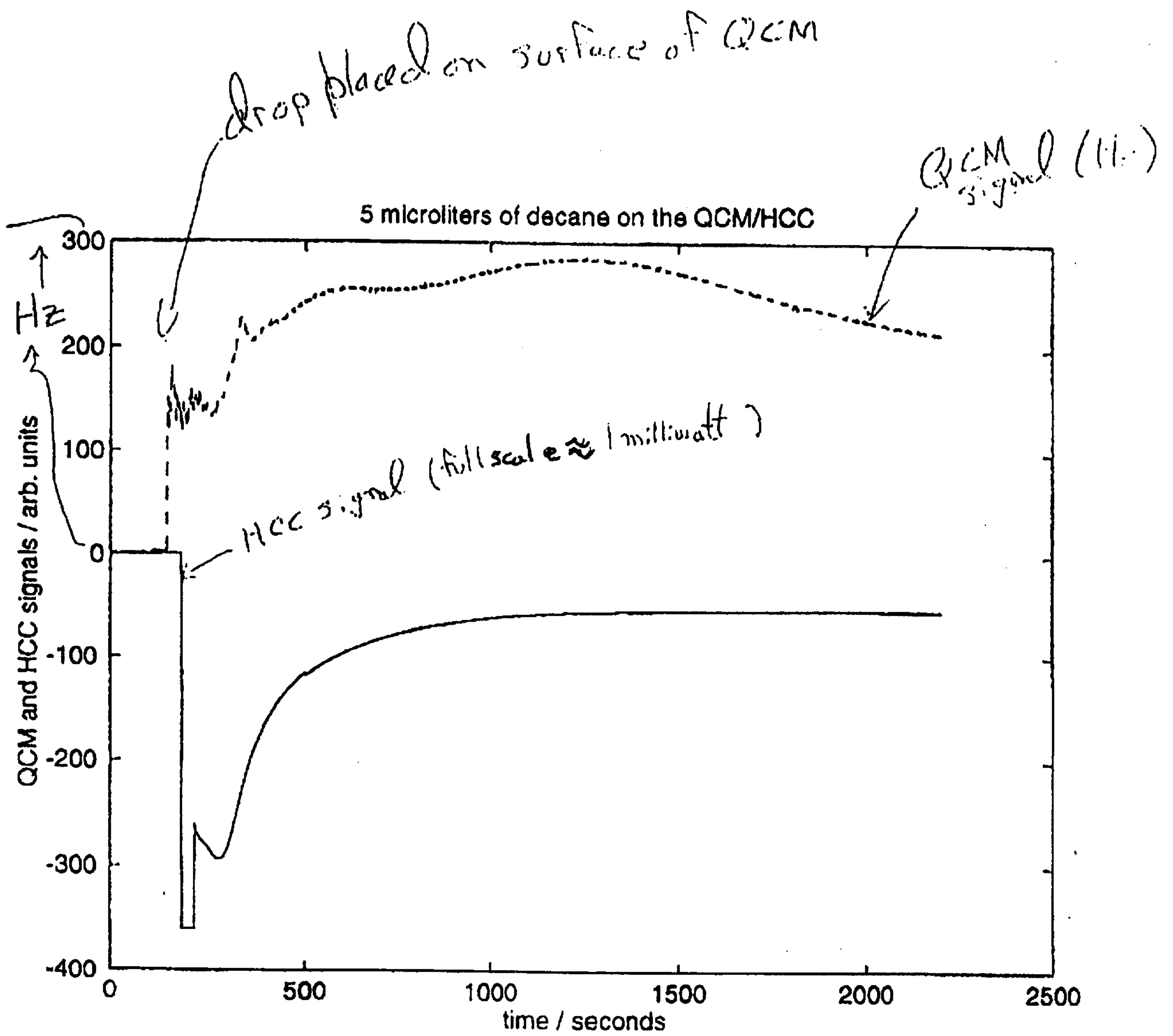


Fig. 7

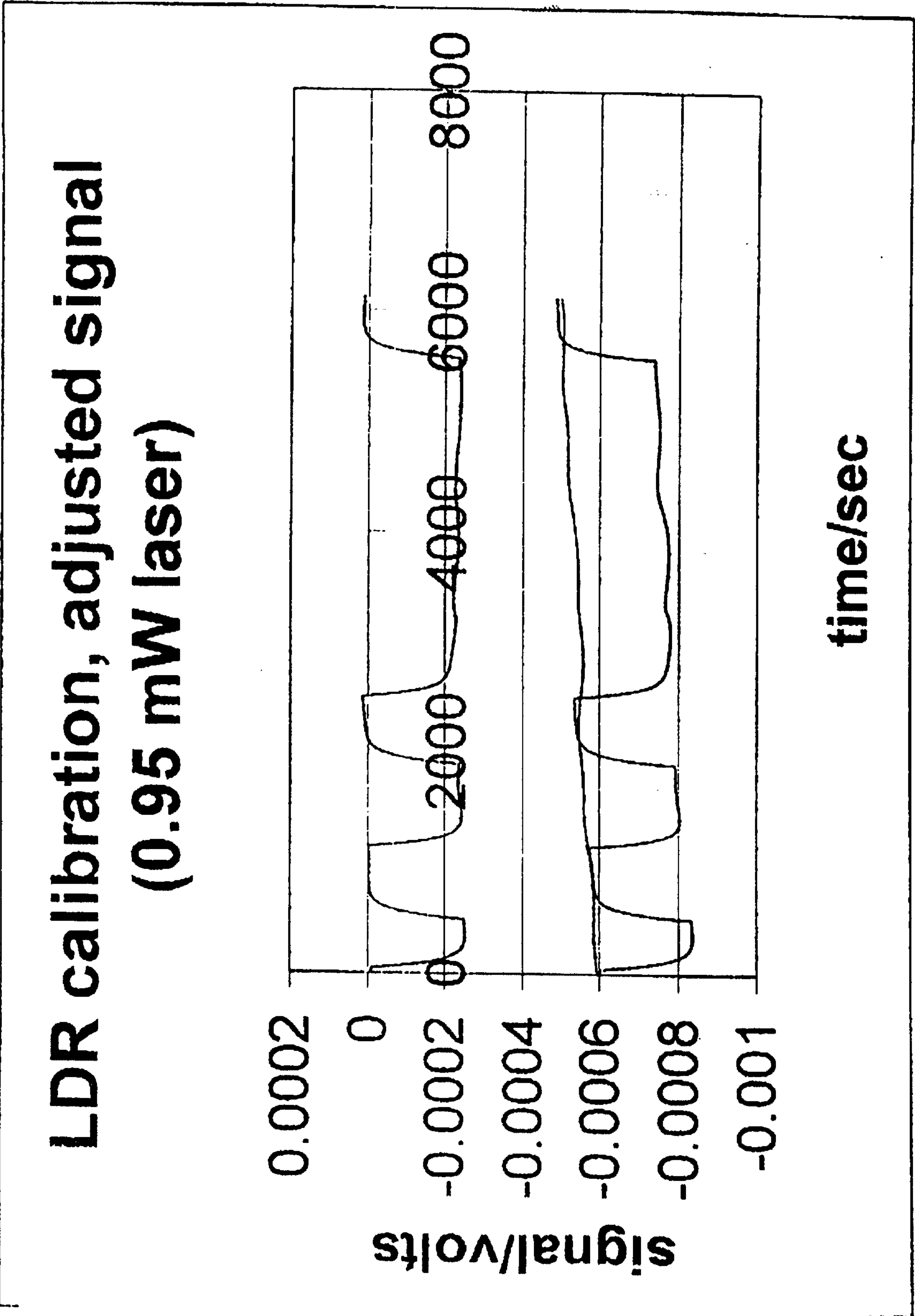


Fig. 8

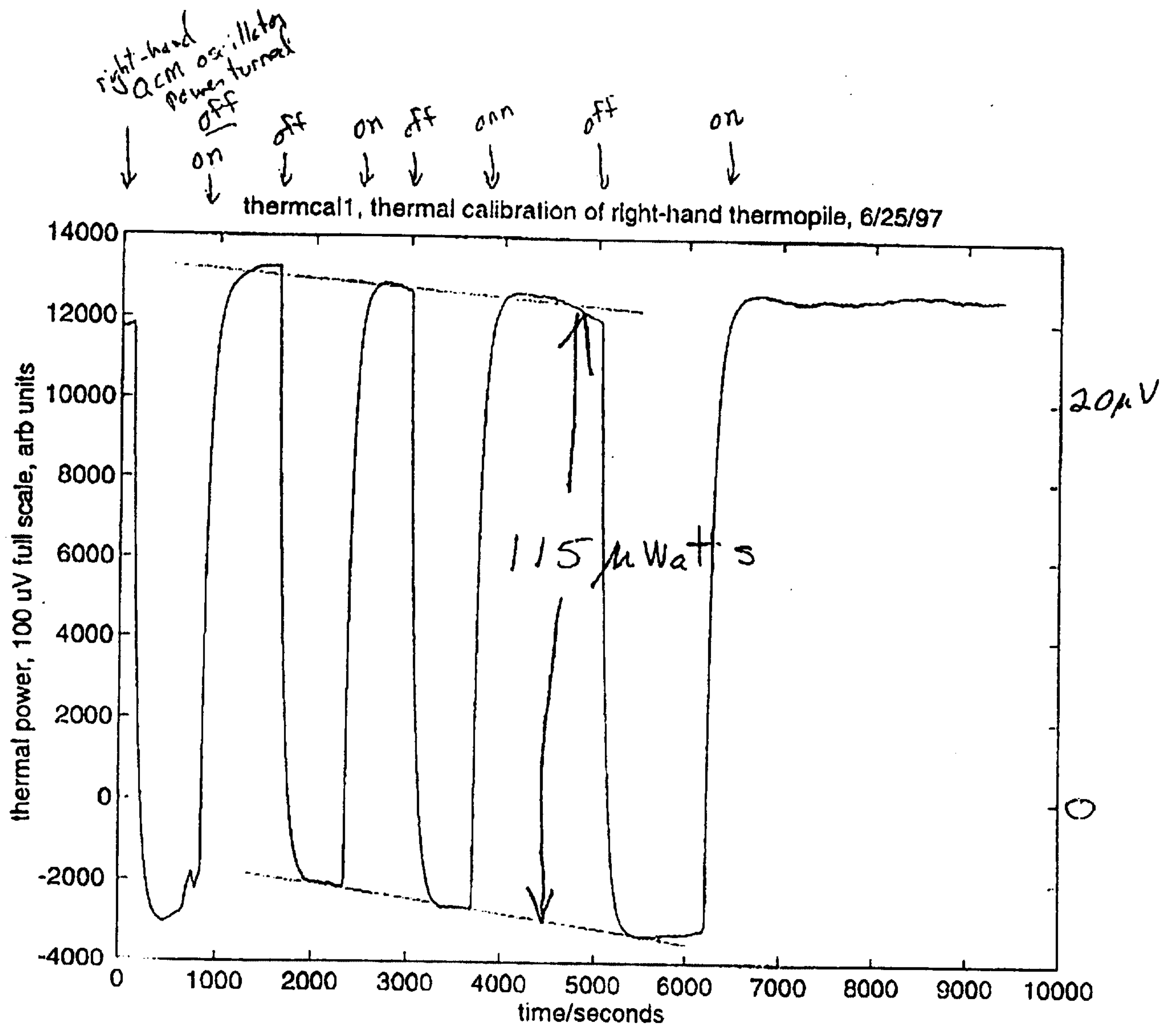


Fig. 9

Signals from QCM and both thermopiles
One drop of hexane deposited on the left side

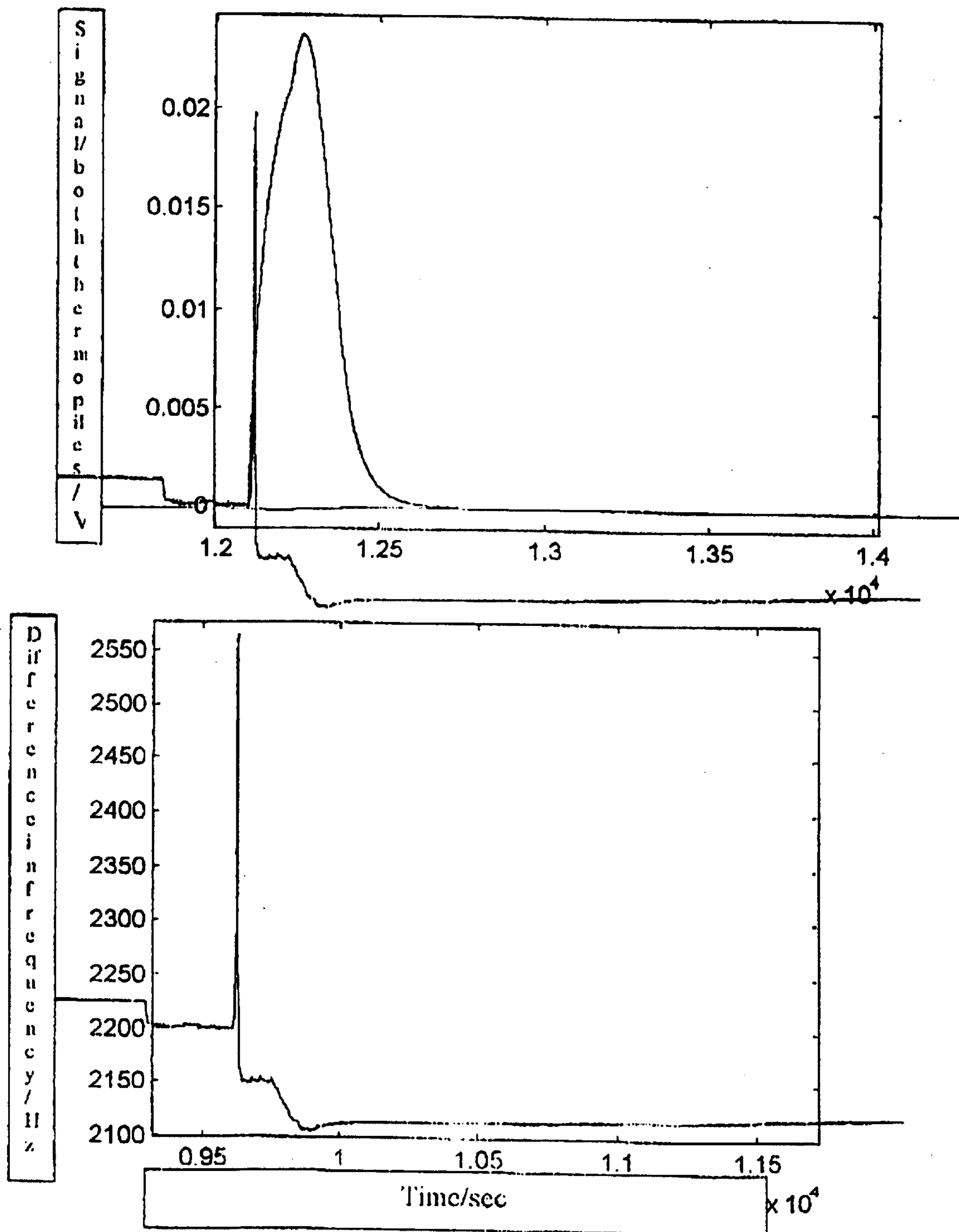


Fig. 10

Signals from QCM and both thermopiles
One drop of hexane deposited on the right side

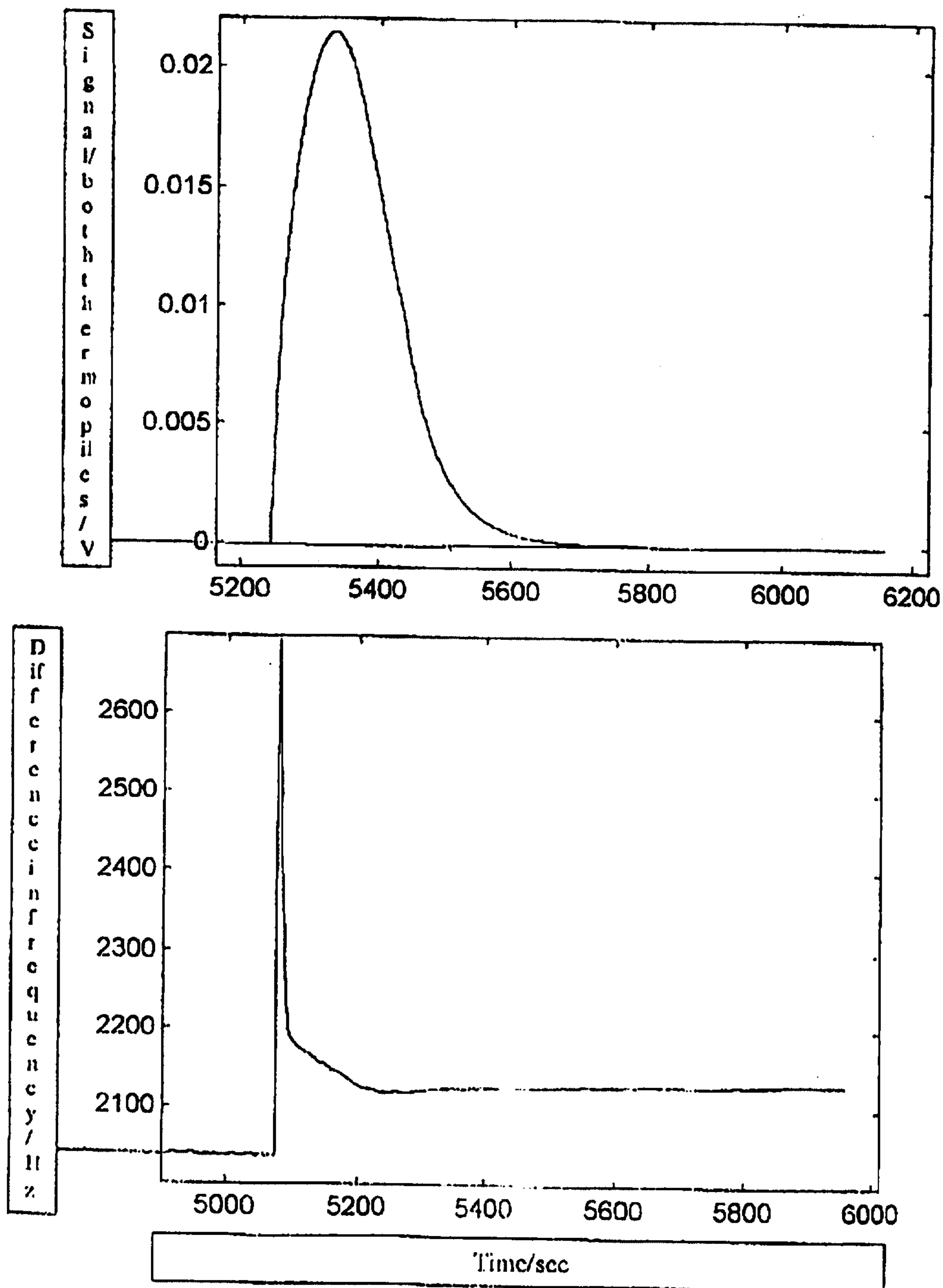


Fig 11

Signals from QCM and both thermopiles

- 1) QCM turned on
- 2) N₂ gas flow, 10 μ l methanol injected (left side)
- 3) 10 μ l methanol injected (right side, vapor)
- 4) 10 μ l methanol injected (left side, vapor)
- 5) 10 μ l hexane injected (left side, vapor)

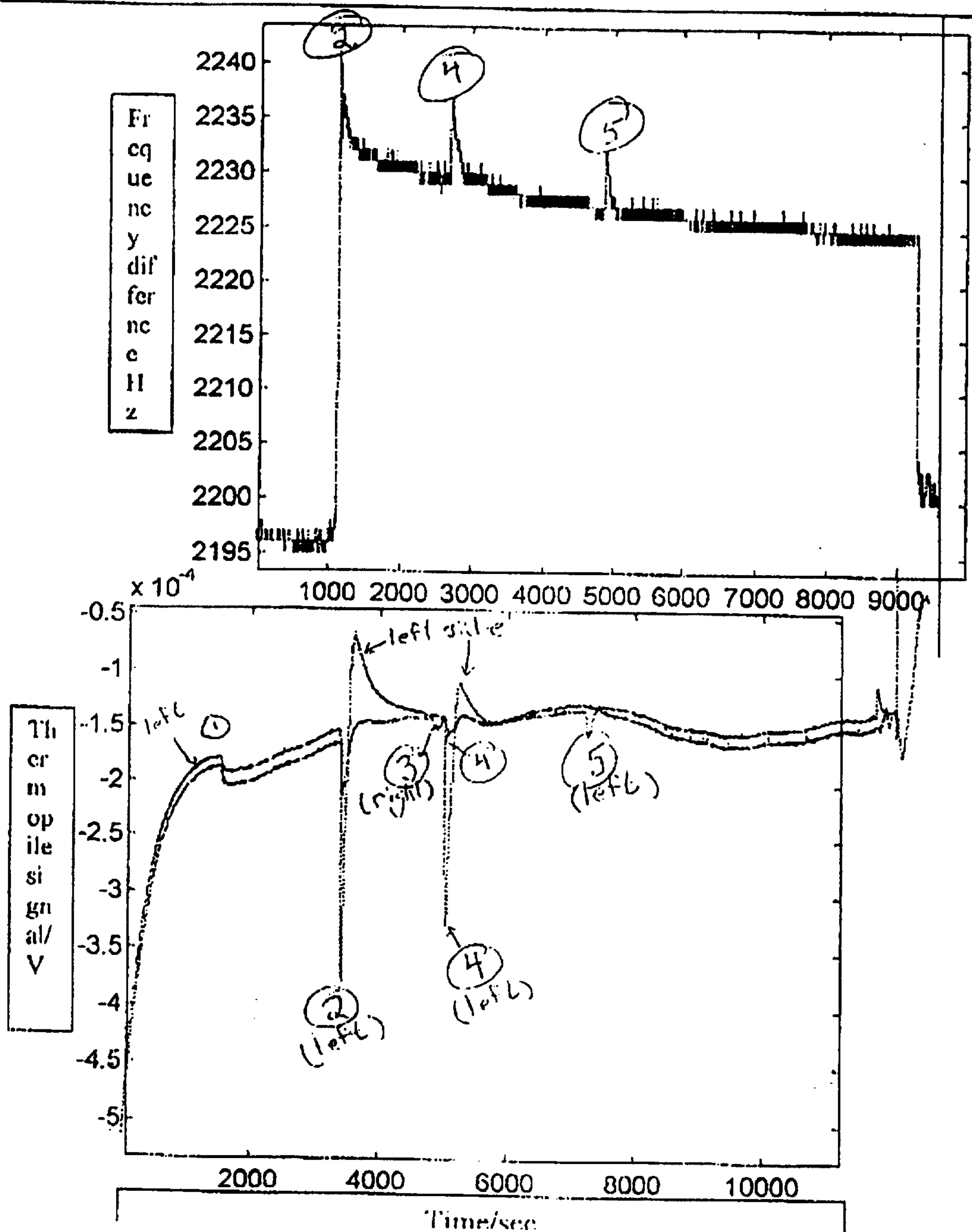


Fig. 12

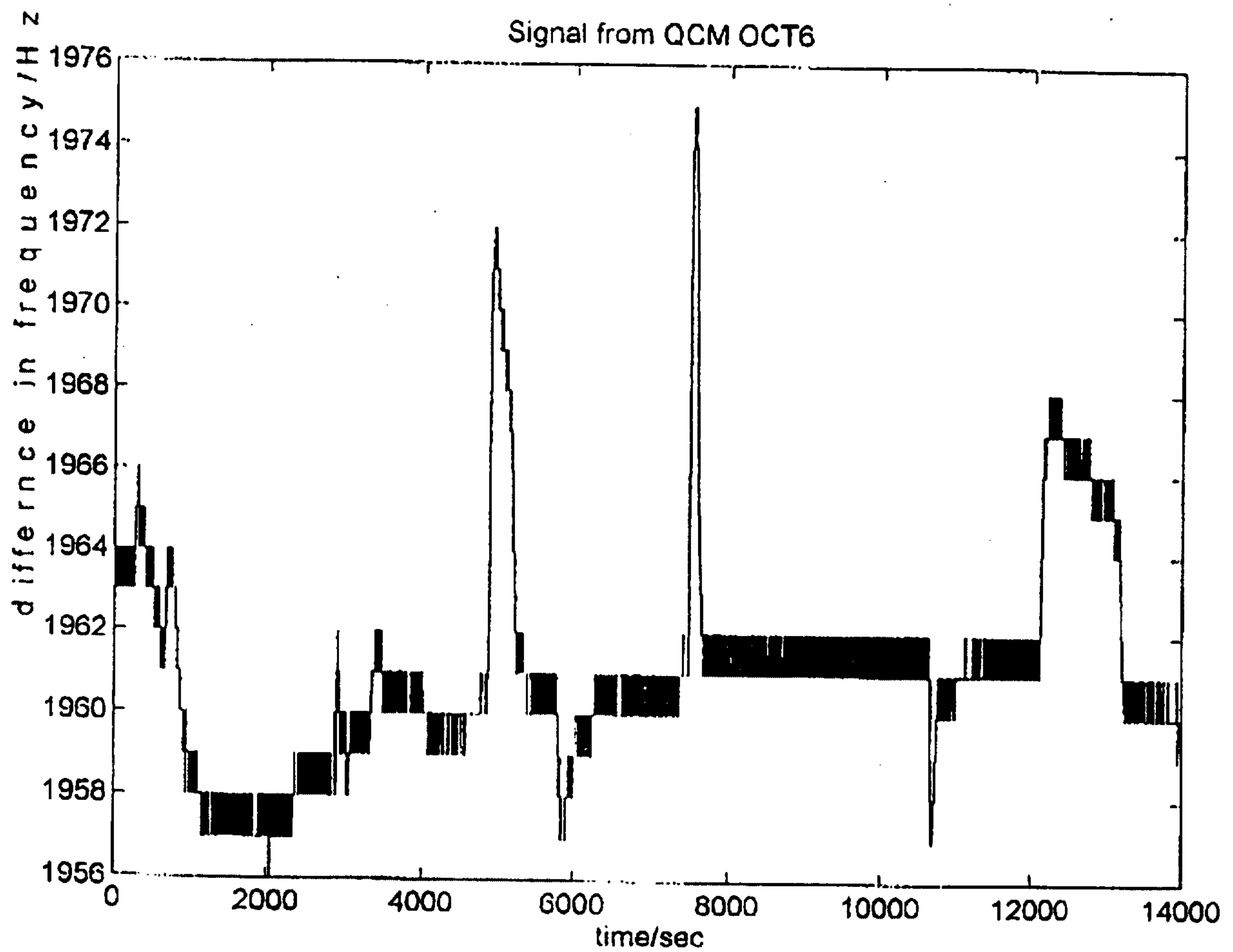


Fig. 13

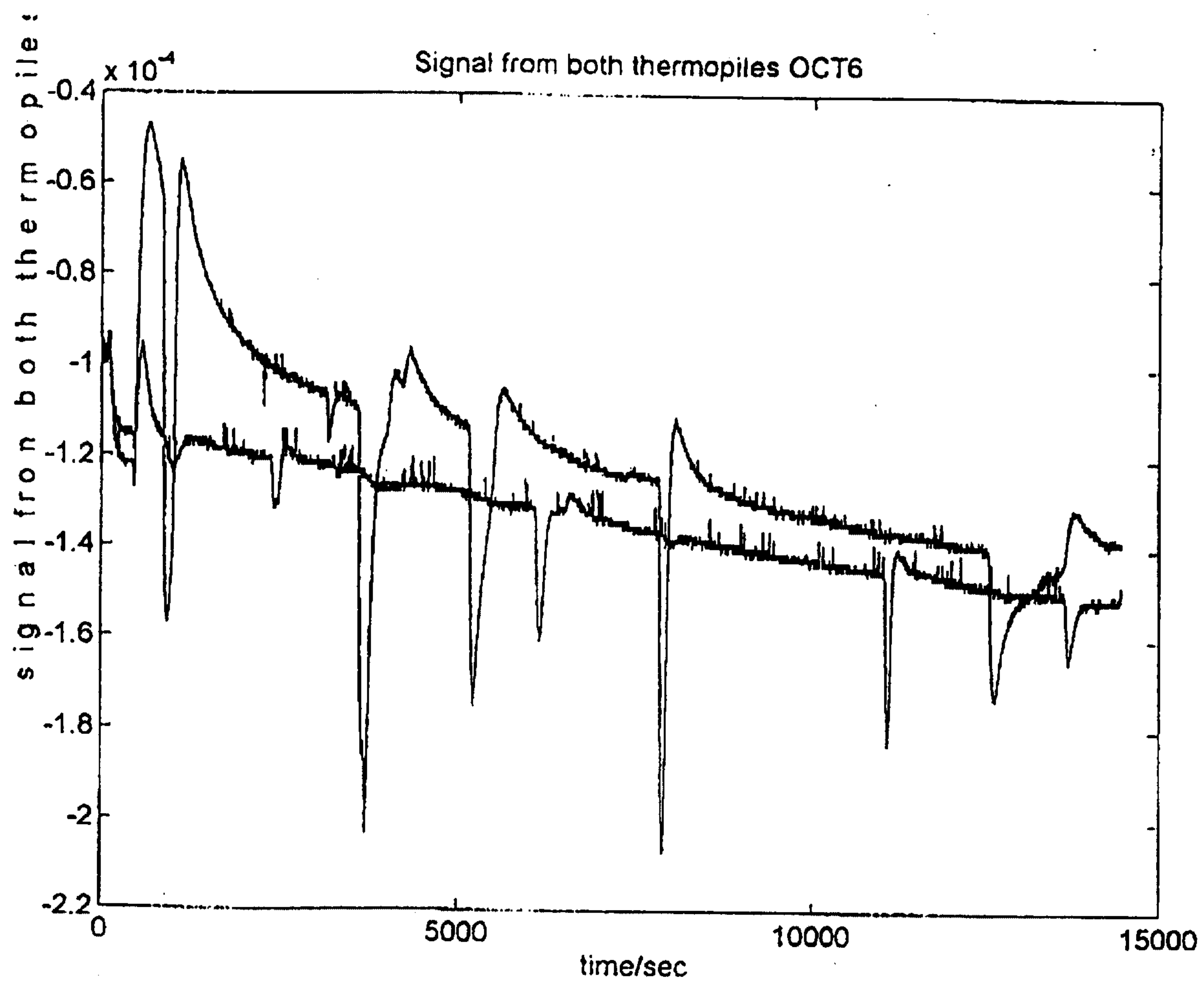


Fig. 14

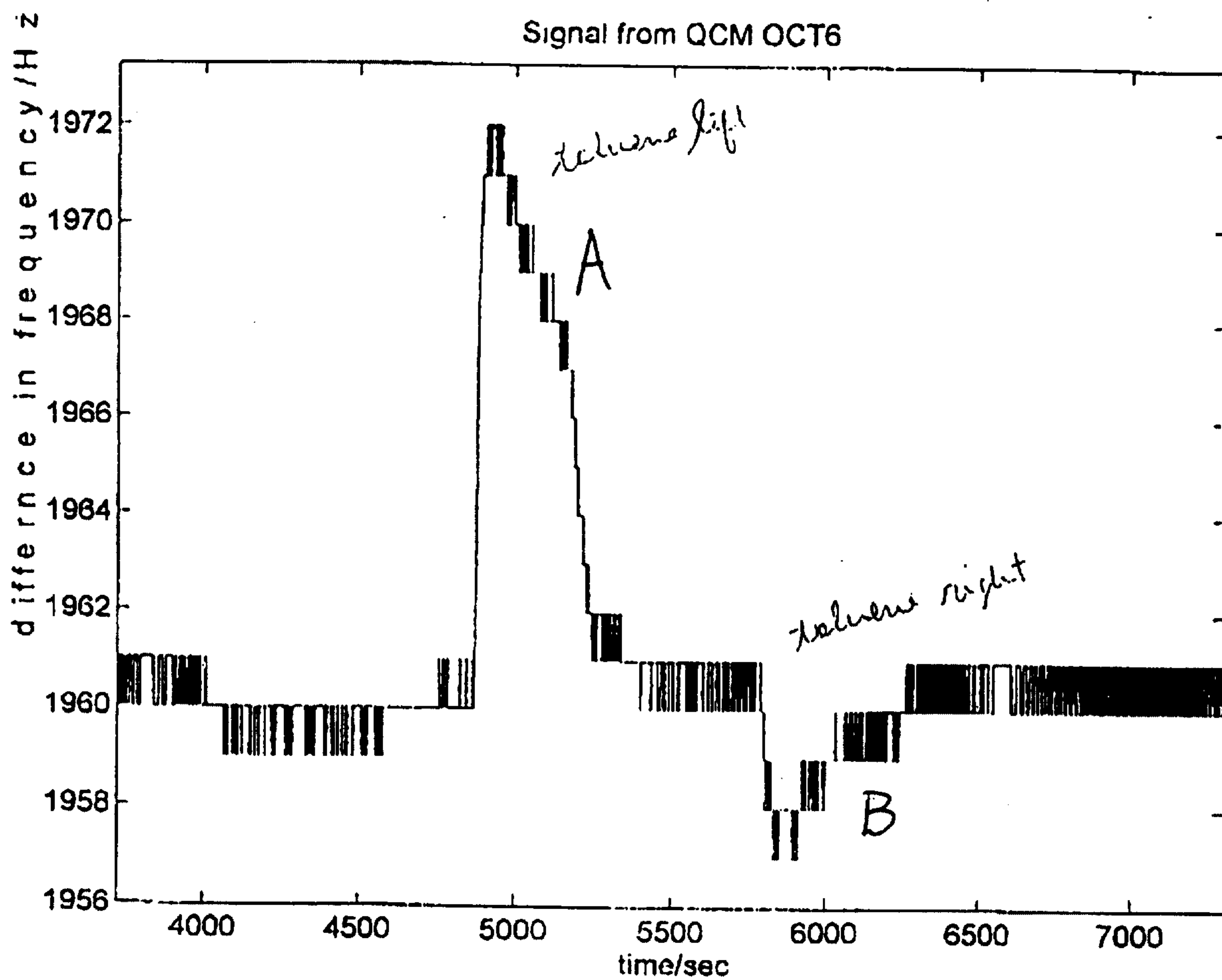


Fig. 15

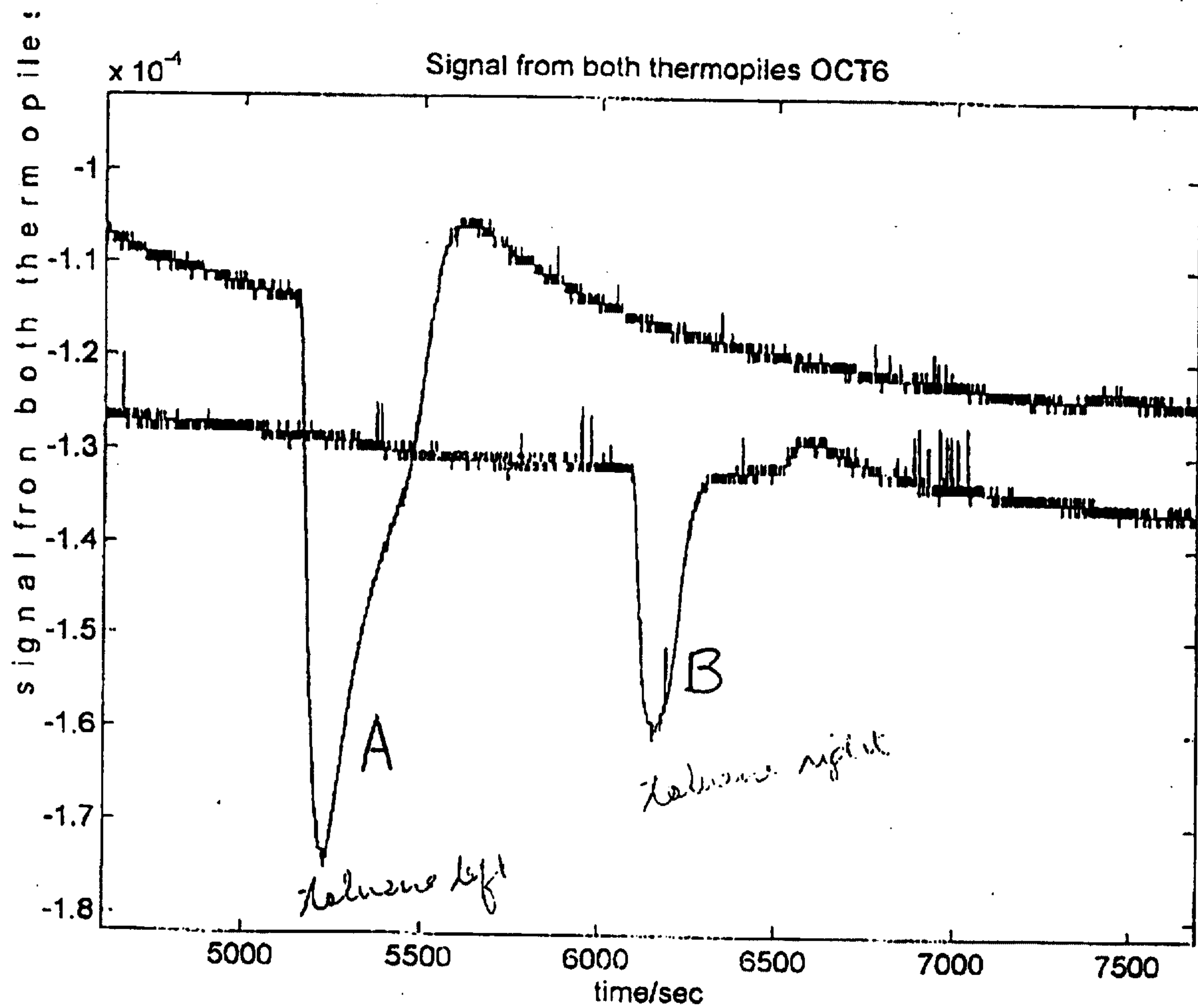


Fig. 16

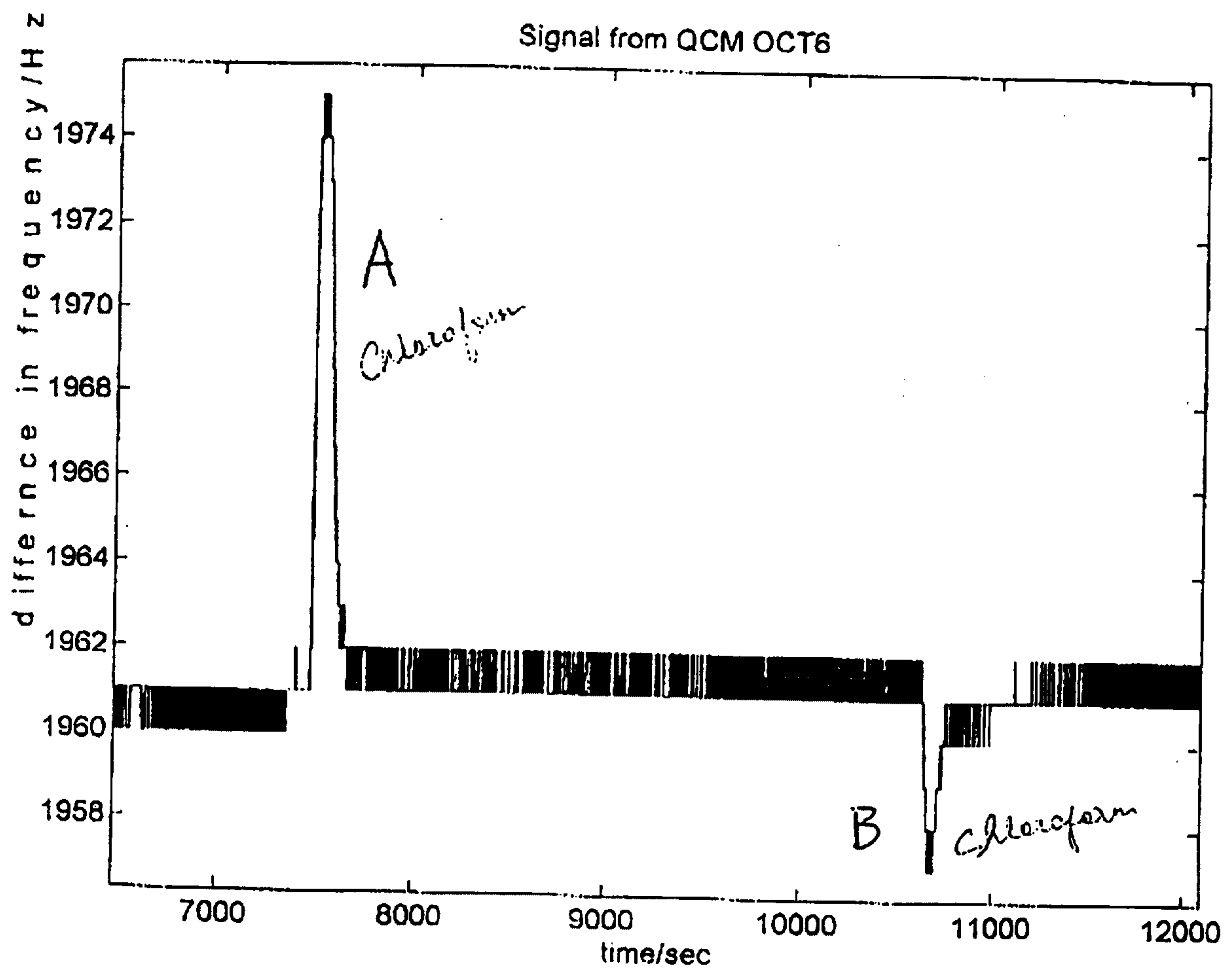


Fig. 17

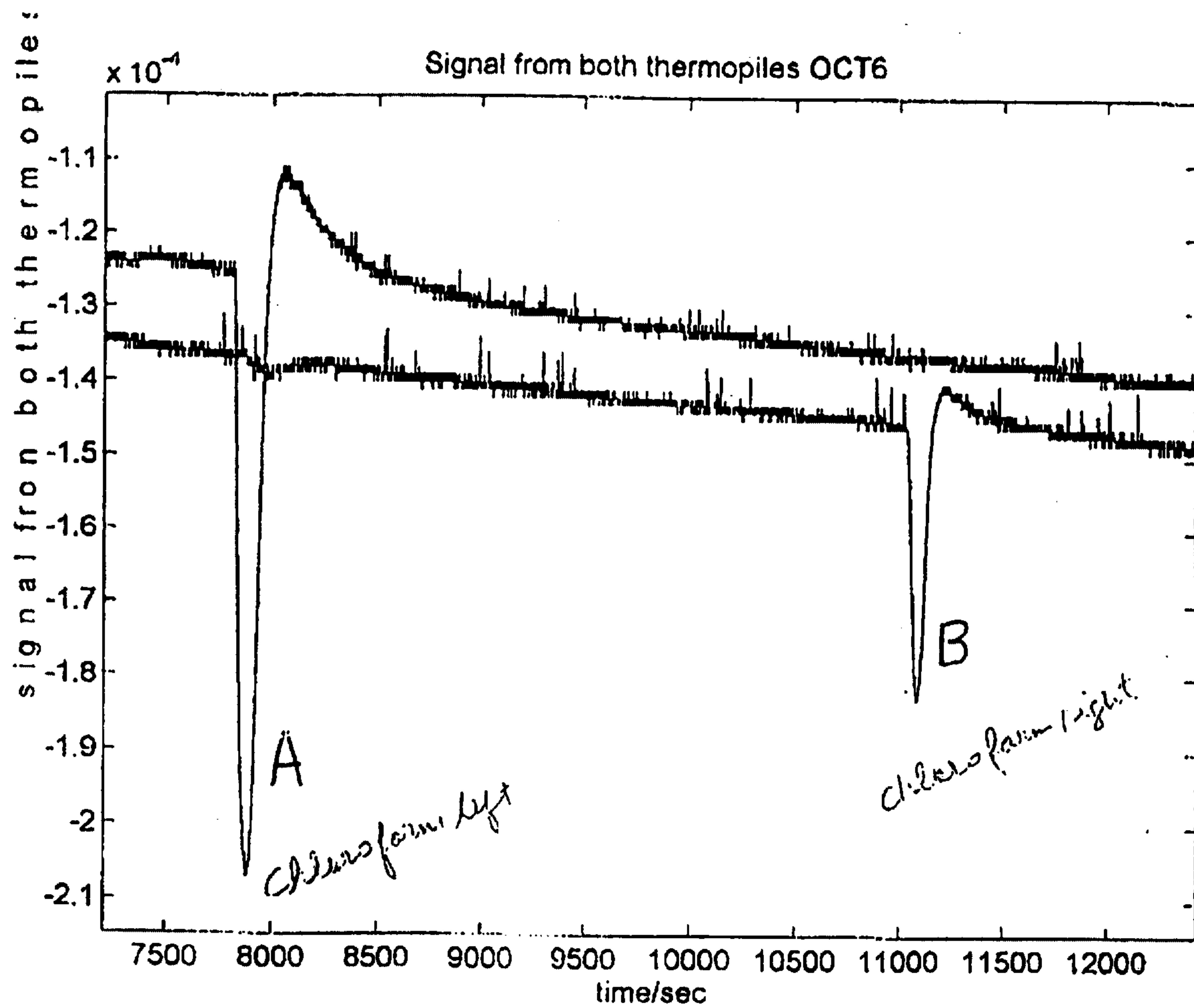


Fig. 18

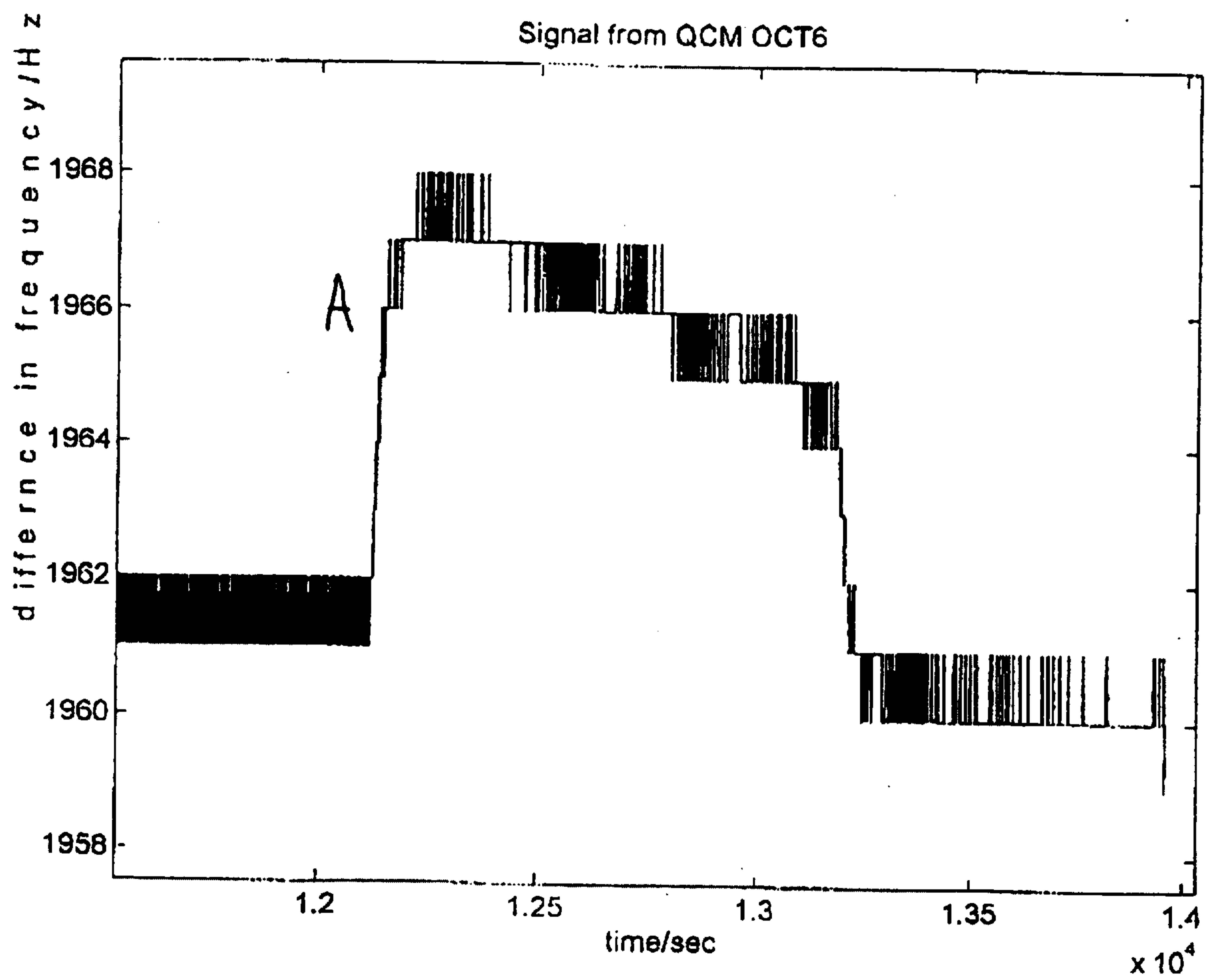


Fig. 19

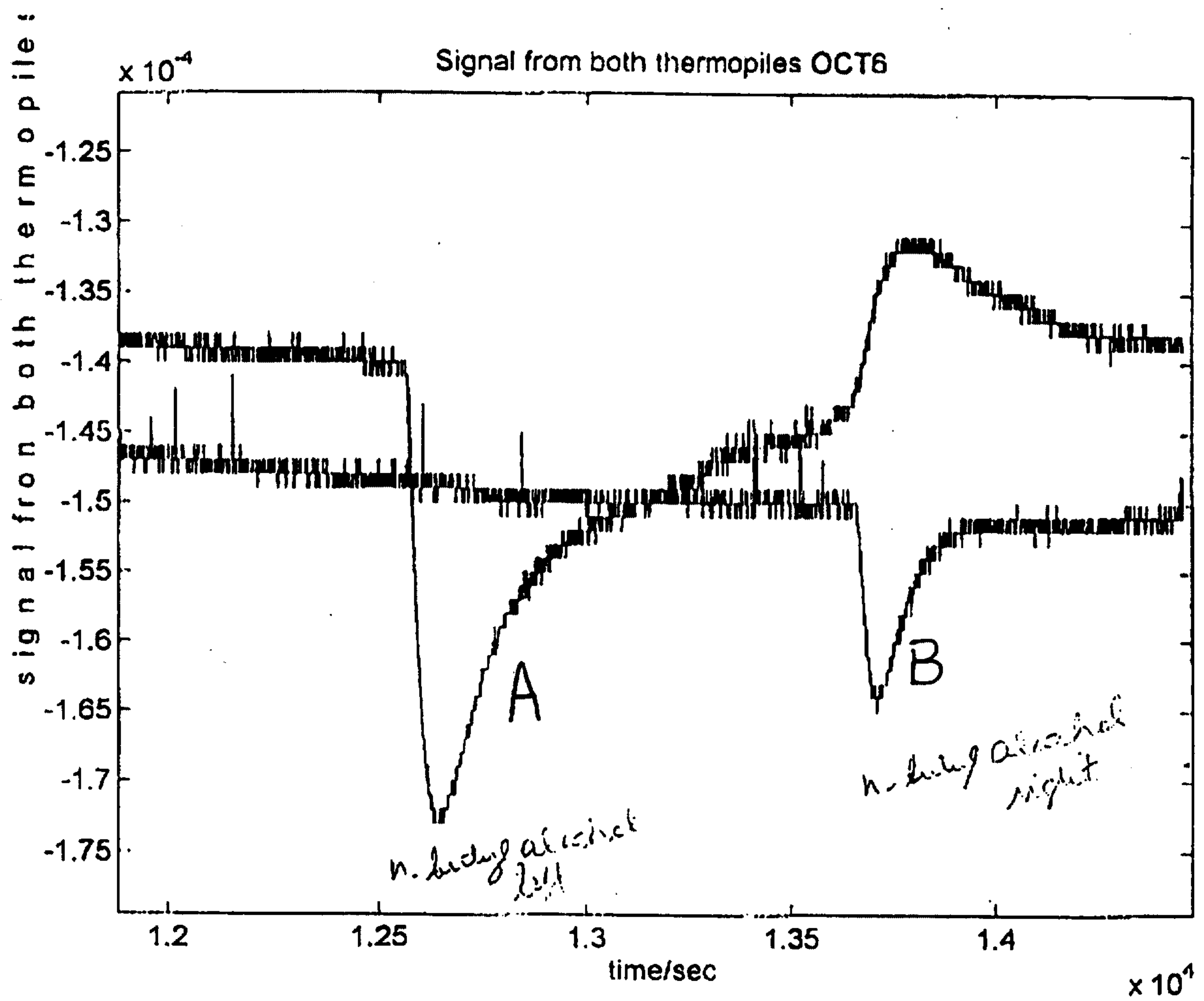


Fig. 20